### **NEXALOGES** Precision Analog Microcontroller, 12-Bit Analog I/O, ARM7TDMI MCU with Enhanced IRQ Handler

# Data Sheet **ADuC7023**

### <span id="page-0-0"></span>**FEATURES**

**Analog I/O Multichannel, 12-bit, 1 MSPS ADC Up to 12 ADC channels Fully differential and single-ended modes 0 V to VREF analog input range 12-bit voltage output DACs 4 DAC outputs available On-chip voltage reference On-chip temperature sensor Voltage comparator Microcontroller ARM7TDMI core, 16-bit/32-bit RISC architecture JTAG port supports code download and debug Clocking options Trimmed on-chip oscillator (±3%) External watch crystal External clock source up to 44 MHz 41.78 MHz PLL with programmable divider Memory 62 kB Flash/EE memory, 8 kB SRAM In-circuit download, JTAG-based debug Software-triggered in-circuit reprogrammability Vectored interrupt controller for FIQ and IRQ 8 priority levels for each interrupt type Interrupt on edge or level external pin inputs On-chip peripherals 2× fully I 2C-compatible channels SPI (20 Mbps in master mode, 10 Mbps in slave mode) With 4-byte FIFO on input and output stages Up to 20 GPIO pins All GPIOs are 5 V tolerant 3× general-purpose timers Watchdog timer (WDT) Programmable logic array (PLA) 16 PLA elements 16-bit, 5-channel PWM Power Specified for 3 V operation Active mode: 11 mA at 5 MHz, 28 mA at 41.78 MHz Packages and temperature range 32-lead 5 mm × 5 mm LFCSP 40-lead LFCSP Fully specified for −40°C to +125°C operation Tools Low cost QuickStart development system Full third-party support**

### **Rev. C**

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### <span id="page-0-1"></span>**APPLICATIONS**

**Optical networking Industrial control and automation systems Smart sensors, precision instrumentation Base station systems**

#### <span id="page-0-2"></span>**GENERAL DESCRIPTION**

The ADuC7023 is a fully integrated, 1 MSPS, 12-bit data acquisition system, incorporating high performance multichannel ADCs, 16-bit/32-bit MCUs, and Flash/EE memory on a single chip.

The ADC consists of up to 12 single-ended inputs. An additional four inputs are available but are multiplexed with the four DAC output pins. The ADC can operate in single-ended or differential input modes. The ADC input voltage is 0 V to  $V_{REF}$ . A low drift band gap reference, temperature sensor, and voltage comparator complete the ADC peripheral set.

The DAC output range is programmable to one of two voltage ranges. The DAC outputs have an enhanced feature of being able to retain their output voltage during a watchdog or software reset sequence.

The devices operate from an on-chip oscillator and a PLL, generating an internal high frequency clock of 41.78 MHz. This clock is routed through a programmable clock divider from which the MCU core clock operating frequency is generated. The microcontroller core is an ARM7TDMI®, 16-bit/32-bit RISC machine that offers up to 41 MIPS peak performance. Eight kilobytes of SRAM and 62 kilobytes of nonvolatile Flash/EE memory are provided on chip. The ARM7TDMI core views all memory and registers as a single linear array.

The ADuC7023 contains an advanced interrupt controller. The vectored interrupt controller (VIC) allows every interrupt to be assigned a priority level. It also supports nested interrupts to a maximum level of eight per IRQ and FIQ. When IRQ and FIQ interrupt sources are combined, a total of 16 nested interrupt levels are supported.

On-chip factory firmware supports in-circuit download via the I<sup>2</sup>C serial interface port, and nonintrusive emulation is supported via the JTAG interface. These features are incorporated into a low cost QuickStart<sup>™</sup> development system supporting this MicroConverter® family. The part contains a 16-bit PWM with five output signals.

For communication purposes, the part contains  $2 \times I^2C$  channels that can be individually configured for master or slave mode. An SPI interface supporting both master and slave modes is also provided.

The parts operate from 2.7 V to 3.6 V and are specified over an industrial temperature range of −40°C to +125°C. The ADuC7023 is available in either a 32-lead or 40-lead LFCSP package.

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### <span id="page-2-0"></span>**REVISION HISTORY**



### **7/10—Rev. A to Rev. B**







### **6/10—Rev. 0 to Rev. A**



**1/10—Revision 0: Initial Version**

### <span id="page-3-0"></span>**FUNCTIONAL BLOCK DIAGRAM**



*Figure 1.* 

## <span id="page-4-0"></span>**SPECIFICATIONS**

 $AV_{DD} = IOV_{DD} = 2.7 V$  to 3.6 V,  $V_{REF} = 2.5 V$  internal reference,  $f_{CORE} = 41.78 MHz$ ,  $T_A = -40°C$  to +125°C, unless otherwise noted.

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<sup>1</sup> All ADC channel specifications are guaranteed during normal microcontroller core operation.

<sup>2</sup> Apply to all ADC input channels.

<sup>3</sup> Measured using the factory-set default values in the ADC offset register (ADCOF) and gain coefficient register (ADCGN).

<sup>4</sup> Not production tested but supported by design and/or characterization data on production release.

<sup>5</sup> Measured using the factory-set default values in ADCOF and ADCGN with an externa[l AD845](http://www.analog.com/AD845) op amp as an input buffer stage as shown i[n Figure 28.](#page-32-2) Based on external ADC system components, the user may need to execute a system calibration to remove external endpoint errors and achieve these specifications (see th[e Calibration](#page-32-1) section).

 $6$  The input signal can be centered on any dc common-mode voltage (V<sub>CM</sub>) as long as this value is within the ADC voltage input range specified.

<sup>7</sup> DAC linearity is calculated using a reduced code range of 100 to 3995.

<sup>8</sup> DAC gain error is calculated using a reduced code range of 100 to internal 2.5 V VREF.

<sup>9</sup> DAC linearity is calculated using a reduced code range of 100 to 3995.

<sup>10</sup> DAC gain error is calculated using a reduced code range of 100 to internal 2.5 V VREF.

<sup>11</sup> Endurance is qualified as per JEDEC Standard 22 Method A117 and measured at −40°C, +25°C, +85°C, and +125°C.

 $^{12}$  Retention lifetime equivalent at junction temperature (T<sub>J</sub>) = 85°C as per JEDEC Standard 22 Method A117. Retention lifetime derates with junction temperature.

<sup>13</sup> Test carried out with a maximum of eight I/Os set to a low output level.

<sup>14</sup> Power supply current consumption is measured in normal, pause, and sleep modes under the following conditions: normal mode with 3.6 V supply, pause mode with 3.6 V supply, and sleep mode with 3.6 V supply.

<sup>15</sup> IOV<sub>DD</sub> power supply current decreases typically by 2 mA during a Flash/EE erase cycle.

### <span id="page-7-0"></span>**TIMING SPECIFICATIONS**

### **Table 2. I2 C Timing in Fast Mode (400 kHz)**



### **Table 3. I2 C Timing in Standard Mode (100 kHz)**





*Figure 2. I2 C-Compatible Interface Timing*

<span id="page-8-1"></span><span id="page-8-0"></span>



 $1$  t<sub>UCLK</sub> = 23.9 ns. It corresponds to the 41.78 MHz internal clock from the PLL before the clock divider.



*Figure 3. SPI Master Mode Timing (Phase Mode = 1)*

### <span id="page-9-1"></span><span id="page-9-0"></span>**Table 5. SPI Master Mode Timing (Phase Mode = 0)**



 $1$  t<sub>UCLK</sub> = 23.9 ns. It corresponds to the 41.78 MHz internal clock from the PLL before the clock divider.



*Figure 4. SPI Master Mode Timing (Phase Mode = 0)*

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### <span id="page-10-0"></span>**Table 6. SPI Slave Mode Timing (Phase Mode = 1)**



 $1$  t<sub>UCLK</sub> = 23.9 ns. It corresponds to the 41.78 MHz internal clock from the PLL before the clock divider.



*Figure 5. SPI Slave Mode Timing (Phase Mode = 1)*

<span id="page-11-1"></span><span id="page-11-0"></span>



 $1$  t<sub>UCLK</sub> = 23.9 ns. It corresponds to the 41.78 MHz internal clock from the PLL before the clock divider.



*Figure 6. SPI Slave Mode Timing (Phase Mode = 0)*

## <span id="page-12-0"></span>ABSOLUTE MAXIMUM RATINGS

 $AGND = GND<sub>REF</sub>, T<sub>A</sub> = 25°C$ , unless otherwise noted.

### **Table 8.**



Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Only one absolute maximum rating can be applied at any one time.

### <span id="page-12-1"></span>**ESD CAUTION**



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

# <span id="page-13-0"></span>PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS



**Table 9. Pin Function Descriptions** 







## <span id="page-16-0"></span>TYPICAL PERFORMANCE CHARACTERISTICS



*Figure 9. Typical DNL, fADC = 950 kSPS, Internal Reference Used*

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*Figure 10. Typical INL, fADC = 950 kSPS, Internal Reference Used*



*Figure 11. Typical DNL, fADC = 950 kSPS, External 1.0 V Reference Used*



*Figure 12. Typical INL, fADC = 950 kSPS, External 1.0 V Reference Used*



*Figure 13. SINAD, THD, and PHSN of ADC , Internal 2.5 V Reference Used*

### <span id="page-17-0"></span>**TERMINOLOGY ADC SPECIFICATIONS**

### <span id="page-17-1"></span>**Integral Nonlinearity (INL)**

The maximum deviation of any code from a straight line passing through the endpoints of the ADC transfer function. The endpoints of the transfer function are zero scale, a point ½ LSB below the first code transition, and full scale, a point ½ LSB above the last code transition.

### **Differential Nonlinearity (DNL)**

The difference between the measured and the ideal 1 LSB change between any two adjacent codes in the ADC.

### **Offset Error**

The deviation of the first code transition (0000 . . . 000) to  $(0000 \dots 001)$  from the ideal, that is,  $+\frac{1}{2}$  LSB.

### **Gain Error**

The deviation of the last code transition from the ideal AIN voltage (full scale − 1.5 LSB) after the offset error has been adjusted out.

### **Signal to (Noise + Distortion) Ratio**

The measured ratio of signal to (noise + distortion) at the output of the ADC. The signal is the rms amplitude of the fundamental. Noise is the rms sum of all nonfundamental signals up to half the sampling frequency  $(f<sub>S</sub>/2)$ , excluding dc. The ratio is dependent upon the number of quantization levels in the digitization process; the more levels, the smaller the quantization noise.

The theoretical signal to (noise + distortion) ratio for an ideal N-bit converter with a sine wave input is given by

*Signal to* (*Noise* + *Distortion*) = (6.02 *N* + 1.76) dB

Thus, for a 12-bit converter, this is 74 dB.

### **Total Harmonic Distortion**

The ratio of the rms sum of the harmonics to the fundamental.

### <span id="page-17-2"></span>**DAC SPECIFICATIONS**

### **Relative Accuracy**

Otherwise known as endpoint linearity, relative accuracy is a measure of the maximum deviation from a straight line passing through the endpoints of the DAC transfer function. It is measured after adjusting for zero error and full-scale error.

### **Voltage Output Settling Time**

The amount of time it takes the output to settle to within a 1 LSB level for a full-scale input change.

## <span id="page-18-0"></span>OVERVIEW OF THE ARM7TDMI CORE

The ARM7® core is a 32-bit reduced instruction set computer (RISC). It uses a single 32-bit bus for instruction and data. The length of the data can be 8 bits, 16 bits, or 32 bits. The length of the instruction word is 32 bits.

The ARM7TDMI is an ARM7 core with four additional features: T support for the thumb (16-bit) instruction set, D support for debug, M support for long multiplications, and I includes the EmbeddedICE module to support embedded system debugging

### <span id="page-18-1"></span>**THUMB MODE (T)**

An ARM instruction is 32 bits long. The ARM7TDMI processor supports a second instruction set that has been compressed into 16 bits, called the Thumb® instruction set. Faster execution from 16-bit memory and greater code density can usually be achieved by using the Thumb instruction set instead of the ARM instruction set, which makes the ARM7TDMI core particularly suitable for embedded applications.

However, the Thumb mode has two limitations. Thumb code typically requires more instructions for the same job. As a result, ARM code is usually best for maximizing the performance of time critical code. Also, the Thumb instruction set does not include some of the instructions needed for exception handling, which automatically switches the core to ARM code for exception handling.

See the ARM7TDMI user guide for details on the core architecture, the programming model, and both the ARM and ARM Thumb instruction sets.

### <span id="page-18-2"></span>**LONG MULTIPLY (M)**

The ARM7TDMI instruction set includes four extra instructions that perform 32-bit by 32-bit multiplication with a 64-bit result, and 32-bit by 32-bit multiplication-accumulation (MAC) with a 64-bit result. These results are achieved in fewer cycles than required on a standard ARM7 core.

### <span id="page-18-3"></span>**EmbeddedICE (I)**

EmbeddedICE provides integrated on-chip support for the core. The EmbeddedICE module contains the breakpoint and watchpoint registers that allow code to be halted for debugging purposes. These registers are controlled through the JTAG test port.

When a breakpoint or watchpoint is encountered, the processor halts and enters debug state. Once in a debug state, the processor registers can be inspected as well as the Flash/EE, SRAM, and memory mapped registers.

### <span id="page-18-4"></span>**EXCEPTIONS**

ARM supports five types of exceptions and a privileged processing mode for each type. The five types of exceptions are:

- Normal interrupt or IRQ. This is provided to service general-purpose interrupt handling of internal and external events.
- Fast interrupt or FIQ. This is provided to service data transfers or communication channels with low latency. FIQ has priority over IRQ.
- Memory abort.
- Attempted execution of an undefined instruction.
- Software interrupt instruction (SWI). This can be used to make a call to an operating system.

Typically, the programmer defines interrupt as IRQ, but for higher priority interrupt, that is, faster response time, the programmer can define interrupt as FIQ.

### <span id="page-18-5"></span>**ARM REGISTERS**

ARM7TDMI has a total of 37 registers: 31 general-purpose registers and six status registers. Each operating mode has dedicated banked registers.

When writing user-level programs, 15 general-purpose 32-bit registers (R0 to R14), the program counter (R15), and the current program status register (CPSR) are usable. The remaining registers are only used for system-level programming and exception handling.

When an exception occurs, some of the standard registers are replaced with registers specific to the exception mode. All exception modes have replacement banked registers for the stack pointer (R13) and the link register (R14) as represented in [Figure 14.](#page-18-6) The fast interrupt mode has more registers (R8 to R12) for fast interrupt processing. This means the interrupt processing can begin without the need to save or restore these registers, and thus save critical time in the interrupt handling process.

<span id="page-18-6"></span>

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More information relative to the model of the programmer and the ARM7TDMI core architecture can be found in ARM7TDMI technical and ARM architecture manuals available directly from ARM Ltd.

### <span id="page-19-0"></span>**INTERRUPT LATENCY**

The worst-case latency for a fast interrupt request (FIQ) consists of the following: the longest time the request can take to pass through the synchronizer, the time for the longest instruction to complete (the longest instruction is an LDM) that loads all the registers including the PC, and the time for the data abort and FIQ entry.

At the end of this time, the ARM7TDMI executes the instruction at 0x1C (FIQ interrupt vector address). The maximum total time is 50 processor cycles, which is just under 1.2 µs in a system using a continuous 41.78 MHz processor clock.

The maximum interrupt request (IRQ) latency calculation is similar but must allow for the fact that FIQ has higher priority and could delay entry into the IRQ handling routine for an arbitrary length of time. This time can be reduced to 42 cycles if the LDM command is not used. Some compilers have an option to compile without using this command. Another option is to run the part in thumb mode where the time is reduced to 22 cycles.

The minimum latency for FIQ or IRQ interrupts is a total of five cycles, which consist of the shortest time the request can take through the synchronizer, plus the time to enter the exception mode.

The ARM7TDMI always runs in ARM (32-bit) mode when in privileged modes, for example, when executing interrupt service routines.

## <span id="page-20-0"></span>MEMORY ORGANIZATION

The ADuC7023 incorporates two separate blocks of memory: 8 kB of SRAM and 64 kB of on-chip Flash/EE memory; 62 kB of on-chip Flash/EE memory is available to the user, and the remaining 2 kB are reserved for the factory configured boot page. These two blocks are mapped as shown i[n Figure 15.](#page-20-5)



*Figure 15. Physical Memory Map*

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<span id="page-20-5"></span>By default, after a reset, the Flash/EE memory is mirrored at Address 0x00000000. It is possible to remap the SRAM at Address 0x00000000 by clearing Bit 0 of the Remap MMR. This remap function is described in more detail in th[e Flash/EE](#page-20-2)  [Memory](#page-20-2) section.

### <span id="page-20-1"></span>**MEMORY ACCESS**

The ARM7 core sees memory as a linear array of the  $2^{32}$  byte location where the different blocks of memory are mapped as outlined in [Figure 15.](#page-20-5)

The ADuC7023 memory organizations are configured in little endian format, which means that the least significant byte is located in the lowest byte address, and the most significant byte is in the highest byte address.



*Figure 16. Little Endian Format*

### <span id="page-20-2"></span>**FLASH/EE MEMORY**

The total 64 kB of Flash/EE memory is organized as  $32k \times 16$  bits;  $31k \times 16$  bits is user space and  $1 k \times 16$  bits is reserved for the on-chip kernel. The page size of this Flash/EE memory is 512 bytes.

62 kilobytes of Flash/EE memory are available to the user as code and nonvolatile data memory. There is no distinction between data and program because ARM code shares the same space. The real width of the Flash/EE memory is 16 bits, which means that in ARM mode (32-bit instruction), two accesses to the Flash/EE are necessary for each instruction fetch. It is, therefore, recommended to use Thumb mode when executing from Flash/EE memory for optimum access speed. The maximum access speed for the Flash/EE memory is 41.78 MHz in Thumb mode and 20.89 MHz in full ARM mode. More details about Flash/EE access time are outlined later in the [Execution Time from SRAM and Flash/EE](#page-39-0) section.

### <span id="page-20-3"></span>**SRAM**

Eight kilobytes of SRAM are available to the user, organized as  $2k \times 32$  bits, that is, two words. ARM code can run directly from SRAM at 41.78 MHz, given that the SRAM array is configured as a 32-bit wide memory array. More details about SRAM access time are outlined later in the [Execution Time from SRAM and](#page-39-0)  [Flash/EE](#page-39-0) section.

### <span id="page-20-4"></span>**MEMORY MAPPED REGISTERS**

The memory mapped register (MMR) space is mapped into the upper two pages of the memory array and accessed by indirect addressing through the ARM7 banked registers.

The MMR space provides an interface between the CPU and all on-chip peripherals. All registers, except the core registers, reside in the MMR area. All shaded locations shown i[n Figure 17](#page-21-0) are unoccupied or reserved locations and should not be accessed by user software[. Table 10](#page-22-0) to [Table](#page-26-0) 23 show the full MMR memory map.

The access time for reading from or writing to an MMR depends on the advanced microcontroller bus architecture (AMBA) bus used to access the peripheral. The processor has two AMBA buses: advanced high performance bus (AHB) used for system modules and advanced peripheral bus (APB) used for lower performance peripheral. Access to the AHB is one cycle, and access to the APB is two cycles. All peripherals on the ADuC7023 are on the APB except the Flash/EE memory and the GPIOs.

<b>0xFFFFFFFF</b>	
0xFFFFF820	<b>FLASH CONTROL</b>
0xFFFFF800	<b>INTERFACE</b>
0xFFFFF46C	GPIO
0xFFFFF400	
0xFFFF0FBF	<b>PWM</b>
0xFFFF0F80	
0xFFFF0B54	PLA
0xFFFF0B00	
0xFFFF0A14	SPI
0xFFFF0A00	
0xFFFF0948	12C1
0xFFFF0900	
0xFFFF0848	12CO
0xFFFF0800	
0xFFFF0620	<b>DAC</b>
0xFFFF0600	
0xFFFF0538 0xFFFF0500	<b>ADC</b>
0xFFFF0490	
0xFFFF048C	<b>BAND GAP</b> <b>REFERENCE</b>
0xFFFF0448	
0xFFFF0440	<b>POWER SUPPLY</b> <b>MONITOR</b>
0xFFFF0420	
0xFFFF0404	PLL <b>AND</b> OSCILI <b>ATOR CONTROI</b>
0xFFFF0370	
0xFFFF0360	WATCHDOG <b>TIMER</b>
0xFFFF0334	<b>GENERAL-PURPOSE</b>
0xFFFF0320	TIMER
0xFFFF0310	
0xFFFF0300	<b>TIMER0</b>
0xFFFF0238	<b>REMAP AND</b>
0xFFFF0220	<b>SYSTEM CONTROL</b>
0xFFFF0140	<b>INTERRUPT</b>
0xFFFF0000	<b>CONTROLLER</b>

<span id="page-21-0"></span>*Figure 17. Memory Mapped Registers*

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### <span id="page-22-1"></span><span id="page-22-0"></span>**Table 10. IRQ Address Base = 0xFFFF0000**



**Table 11. System Control Address Base = 0xFFFF0200**



<sup>1</sup> N/A means not applicable.

<sup>2</sup> Updated by kernel.

#### <span id="page-23-0"></span>**Table 12. Timer Address Base = 0xFFFF0300**



<sup>1</sup> N/A means not applicable.

### **Table 13. PLL/PSM Base Address = 0xFFFF0400**



<sup>1</sup> N/A means not applicable.

### **Table 14. Reference Base Address = 0xFFFF0480**



### **Table 15. ADC Address Base = 0xFFFF0500**





### **Table 16. DAC Address Base = 0xFFFF0600**



### **Table 17. I2 C0 Base Address = 0XFFFF0800**



### **Table 18. I2 C1 Base Address = 0XFFFF0900**





### **Table 19. SPI Base Address = 0xFFFF0A00**



### **Table 20. PLA Base Address = 0XFFFF0B00**



### **Table 21. PWM Base Address = 0xFFFF0F80**



### **Table 22. GPIO Base Address = 0xFFFFF400**



### <span id="page-26-0"></span>**Table 23. Flash/EE Base Address = 0xFFFFF800**



## <span id="page-27-0"></span>ADC CIRCUIT OVERVIEW

The analog-to-digital converter (ADC) incorporates a fast, multichannel, 12-bit ADC. It can operate from 2.7 V to 3.6 V supplies and is capable of providing a throughput of up to 1 MSPS when the clock source is 41.78 MHz. This block provides the user with a multichannel multiplexer, a differential track-and-hold, an on-chip reference, and an ADC.

The ADC consists of a 12-bit successive approximation converter based around two capacitor DACs. Depending on the input signal configuration, the ADC can operate in one of three different modes: fully differential mode (for small and balanced signals), single-ended mode (for any single-ended signals), or pseudo differential mode (for any single-ended signals), taking advantage of the common-mode rejection offered by the pseudo differential input.

The converter accepts an analog input range of  $0 \,$ V to  $V_{REF}$  when operating in single-ended or pseudo differential mode. In fully differential mode, the input signal must be balanced around a common-mode voltage ( $V_{CM}$ ) in the 0 V to AV<sub>DD</sub> range with a maximum amplitude of 2  $V_{REF}$  (see [Figure 18\)](#page-27-2).



<span id="page-27-2"></span>*Figure 18. Examples of Balanced Signals in Fully Differential Mode*

A high precision, low drift, factory calibrated, 2.5 V reference is provided on chip. An external reference can also be connected as described later in the [Band Gap Reference](#page-34-0) section.

Single or continuous conversion modes can be initiated in the software. An external CONV<sub>START</sub> pin, an output generated from the on-chip PLA, or a Timer0 or Timer1 overflow can also be used to generate a repetitive trigger for ADC conversions.

A voltage output from an on-chip band gap reference proportional to absolute temperature can also be routed through the front-end ADC multiplexer. This temperature channel can be selected as an ADC input. This facilitates an internal temperature sensor channel that measures die temperature.

### <span id="page-27-1"></span>**TRANSFER FUNCTION**

### *Pseudo Differential and Single-Ended Modes*

In pseudo differential or single-ended mode, the input range is 0 V to V<sub>REF</sub>. The output coding is straight binary in pseudo differential and single-ended modes with

1 LSB = *FS*/4096, or  $2.5 \text{ V}/4096 = 0.61 \text{ mV}$ , or 610  $\mu$ V when  $V_{REF}$  = 2.5 V The ideal code transitions occur midway between successive integer LSB values (that is, 1/2 LSB, 3/2 LSB, 5/2 LSB, … , FS − 3/2 LSB). The ideal input/output transfer characteristic is shown in [Figure 19.](#page-27-3)



<span id="page-27-3"></span>*Figure 19. ADC Transfer Function in Pseudo Differential or Single-Ended Mode* 

### *Fully Differential Mode*

The amplitude of the differential signal is the difference between the signals applied to the V<sub>IN+</sub> and V<sub>IN-</sub> pins (that is, V<sub>IN+</sub> – VIN−). The maximum amplitude of the differential signal is, therefore,  $-V_{REF}$  to  $+V_{REF}$  p-p (that is,  $2 \times V_{REF}$ ). This is regardless of the common mode (CM). The common mode is the average of the two signals, for example,  $(V_{IN+} + V_{IN-})/2$ , and is, therefore, the voltage on which the two inputs are centered. This results in the span of each input being CM  $\pm$ V<sub>REF</sub>/2. This voltage has to be set up externally, and its range varies with  $V_{REF}$  (see the Driving [the Analog Inputs](#page-32-0) section).

The output coding is twos complement in fully differential mode with 1 LSB = 2 VREF/4096 or  $2 \times 2.5$  V/4096 = 1.22 mV when  $V_{REF}$  = 2.5 V. The output result is  $\pm$ 11 bits, but this is shifted by one to the right. This allows the result in the ADCDAT MMR to be declared as a signed integer when writing C code. The designed code transitions occur midway between successive integer LSB values (that is, 1/2 LSB, 3/2 LSB, 5/2 LSB, … , FS − 3/2 LSB). The ideal input/output transfer characteristic is shown in [Figure 20.](#page-27-4)



<span id="page-27-4"></span>*Figure 20. ADC Transfer Function in Differential Mode*

### <span id="page-28-0"></span>**TYPICAL OPERATION**

When configured via the ADC control and channel selection registers, the ADC converts the analog input and provides a 12-bit result in the ADC data register.

The top four bits are the sign bits. The 12-bit result is placed from Bit 16 to Bit 27 as shown in [Figure 21.](#page-28-2) Note that in fully differential mode, the result is represented in twos complement format. In pseudo differential and single-ended modes, the result is represented in straight binary format.



<span id="page-28-2"></span>The same format is used in DACxDAT, simplifying the software.

### *Current Consumption*

The ADC in standby mode, that is, powered up but not converting, typically consumes 640 µA. The internal reference adds 140 µA. During conversion, the extra current is 0.3 µA multiplied by the sampling frequency (in kHz).

### *Timing*

[Figure 22](#page-28-3) gives details of the ADC timing. Users control the ADC clock speed and the number of acquisition clocks in the ADCCON MMR. By default, the acquisition time is eight clocks, and the clock divider is two. The number of extra clocks (such as bit trial or write) is set to 19, which gives a sampling rate of 774 kSPS. For conversion on the temperature sensor, set ADCCON = 0x37A3. When using multiple channels including the temperature sensor, the timing settings revert to the userdefined settings after reading the temperature sensor channel.



### <span id="page-28-3"></span><span id="page-28-1"></span>**MMR INTERFACE**

The ADC is controlled and configured via the eight MMRs described in this section.

### *ADCCON Register*





#### <span id="page-28-4"></span>**Table 24. ADCCON MMR Bit Designations**



### *ADCCP Register*



### <span id="page-29-0"></span>**Table 25. ADCCP MMR Bit Designation**



<sup>1</sup> When a selected ADC channel is shared with one GPIO, by default, this pin is configured with a weak pull-up resistor enabled. The pull-up resistor should be disabled manually in the appropriate GPxPAR register. Note the internal pull-up resistor on P2.0/AIN12 for 40-lead package cannot be disabled.

### *ADCCN Register*



#### <span id="page-30-0"></span>**Table 26. ADCCN MMR Bit Designation Bit Value Description**



### *ADCSTA Register*



### *ADCRST Register*



[Figure 21.](#page-28-2)

### *ADCGN Register*



### *ADCOF Register*



### <span id="page-31-0"></span>**CONVERTER OPERATION**

The ADC incorporates a successive approximation (SAR) architecture involving a charge-sampled input stage. This architecture can operate in three different modes: differential, pseudo differential, and single-ended.

### *Differential Mode*

The ADuC7023 contains a successive approximation ADC based on two capacitive DACs. [Figure 23](#page-31-1) and [Figure 24](#page-31-2) show simplified schematics of the ADC in acquisition and conversion phase, respectively. The ADC is comprised of control logic, a SAR, and two capacitive DACs. I[n Figure 23](#page-31-1) (the acquisition phase), SW3 is closed and SW1 and SW2 are in Position A. The comparator is held in a balanced condition, and the sampling capacitor arrays acquire the differential signal on the input.



<span id="page-31-1"></span>*Figure 23. ADC Acquisition Phase*



*Figure 24. ADC Conversion Phase*

<span id="page-31-2"></span>When the ADC starts a conversion, as shown i[n Figure 24,](#page-31-2) SW3 opens, and then SW1 and SW2 move to Position B. This causes the comparator to become unbalanced. Both inputs are disconnected once the conversion begins. The control logic and the charge redistribution DACs are used to add and subtract fixed amounts of charge from the sampling capacitor arrays to bring the comparator back into a balanced condition. When the comparator is rebalanced, the conversion is complete. The control logic generates the ADC output code. The output impedances of the sources driving the  $V_{IN+}$  and  $V_{IN-}$  pins must be matched; otherwise, the two inputs have different settling times, resulting in errors.

### *Pseudo Differential Mode*

In pseudo differential mode, Channel– is linked to the V<sub>IN</sub>− pin of the ADuC7023 SW2 switches between A (Channel−) and B (VREF). VIN− pin must be connected to ground or a low voltage. The input signal on  $V_{IN+}$  can then vary from  $V_{IN-}$  to  $V_{REF} + V_{IN-}$ .  $V_{IN-}$  must be chosen so that  $V_{REF} + V_{IN-}$  does not exceed AV<sub>DD</sub>.



*Figure 25. ADC in Pseudo Differential Mode*

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### *Single-Ended Mode*

In single-ended mode, SW2 is always connected internally to ground. The V<sub>IN-</sub> pin can be floating. The input signal range on  $V_{IN+}$  is 0 V to  $V_{REF}$ .



### *Analog Input Structure*

[Figure 27](#page-32-3) shows the equivalent circuit of the analog input structure of the ADC. The four diodes provide ESD protection for the analog inputs. Care must be taken to ensure that the analog input signals never exceed the supply rails by more than 300 mV; this causes these diodes to become forward-biased and start conducting into the substrate. These diodes can conduct up to 10 mA without causing irreversible damage to the part.

The C1 capacitors i[n Figure 27](#page-32-3) are typically 4 pF and can be primarily attributed to pin capacitance. The resistors are lumped components made up of the on resistance of the switches. The value of these resistors is typically about 100  $Ω$ . The C2 capacitors are the ADC sampling capacitors and typically have a capacitance of 16 pF.



<span id="page-32-3"></span>*Figure 27. Equivalent Analog Input Circuit Conversion Phase: Switches Open, Track Phase: Switches Closed*

For ac applications, removing high frequency components from the analog input signal is recommended by using an RC lowpass filter on the relevant analog input pins. In applications where harmonic distortion and signal-to-noise ratio are critical, the analog input should be driven from a low impedance source. Large source impedances significantly affect the ac performance of the ADC. This can necessitate the use of an input buffer amplifier. The choice of the op amp is a function of the particular application[. Figure 28](#page-32-2) an[d Figure 29](#page-32-4) give an example of an ADC front end.



<span id="page-32-2"></span>

*Figure 29. Buffering Differential Inputs*

<span id="page-32-4"></span>When no amplifier is used to drive the analog input, limit the source impedance to values lower than 1 kΩ. The maximum source impedance depends on the amount of total harmonic distortion (THD) that can be tolerated. The THD increases as the source impedance increases and the performance degrades.

### <span id="page-32-0"></span>**DRIVING THE ANALOG INPUTS**

Internal or external references can be used for the ADC. When operating in differential mode, there are restrictions on the common-mode input signal ( $V<sub>CM</sub>$ ), which is dependent upon the reference value and supply voltage used to ensure that the signal remains within the supply rails[. Table 27](#page-32-5) gives some calculated  $V_{CM}$  minimum and  $V_{CM}$  maximum values.



### <span id="page-32-5"></span>**Table 27. VCM Ranges**

### <span id="page-32-1"></span>**CALIBRATION**

By default, the factory-set values written to the ADC offset (ADCOF) and gain coefficient registers (ADCGN) yield optimum performance in terms of endpoint errors and linearity for standalone operation of the part (see th[e Specifications](#page-4-0) section). If system calibration is required, it is possible to modify the default offset and gain coefficients to improve endpoint errors, but note that any modification to the factoryset ADCOF and ADCGN values can degrade ADC linearity performance.

For system offset error correction, the ADC channel input stage must be tied to AGND. A continuous software ADC conversion loop must be implemented by modifying the value in ADCOF until the ADC result (ADCDAT) reads Code 0 to Code 1. If the ADCDAT value is greater than 1, ADCOF should be decremented until ADCDAT reads Code 0 to Code 1. Offset error correction is done digitally and has a resolution of 0.25 LSB and a range of  $\pm$ 3.125% of  $V<sub>REF</sub>$ .

For system gain error correction, the ADC channel input stage must be tied to  $V_{REF}$ . A continuous software ADC conversion loop must be implemented to modify the value in ADCGN until the ADCDAT reads Code 4094 to Code 4095. If the ADCDAT value is less than 4094, ADCGN should be incremented until ADCDAT reads Code 4094 to Code 4095. Similar to the offset calibration, the gain calibration resolution is 0.25 LSB with a range of  $\pm 3\%$  of  $V_{REF}$ .

### <span id="page-33-0"></span>**TEMPERATURE SENSOR**

The ADuC7023 provides a voltage output from an on-chip band gap reference that is proportional to absolute temperature. This voltage output can also be routed through the front-end ADC multiplexer (effectively an additional ADC channel input), facilitating an internal temperature sensor channel, measuring die temperature.

An ADC temperature sensor conversion differs from a standard ADC voltage. The ADC performance specifications do not apply to the temperature sensor.

Chopping of the internal amplifier should be enabled using the TSCON register. To enable this mode, the user must set Bit 0 of TSCON. The user must also take two consecutive ADC readings and average them in this mode.

The ADCCON register must be configured to 0x37A3.

To calculate die temperature use the following formula:

 $T - T_{RFF} = (V_{ADC} - V_{TREF}) \times K$ 

where:

T is the temperature result.

TREF is 25°C.

VADC is the average ADC result from two consecutive conversions.

 $V<sub>TREF</sub>$  is 1369 mV, which corresponds to  $T<sub>REF</sub> = 25°C$  as described in [Table 1.](#page-4-1)

K is the gain of the ADC in temperature sensor mode as determined by characterization data,  $K = 0.2262$ °C/mV. This corresponds to 1/V TC specification as shown i[n Table 1.](#page-4-1)

Using the default values from [Table 1](#page-4-1) and without any calibration, this equation becomes

*T* – 25°C = (*VADC* − 1369) × 0.2262

where:

*VADC* is in millivolts.

For increased accuracy, perform a single point calibration at a controlled temperature value.

For the calculation shown without calibration,  $(T_{REF}, V_{TREF}) =$ (25°C, 1369 mV). The idea of a single point calibration is to use other known (TREF, VTREF) values to replace the common (25 $^{\circ}$ C, 1369 mV) for every part.

For some users, it is not possible to get such a known pair. For these cases, an ADuC7023 comes with a single point calibration value loaded in the TEMPREF register. For more details on this register, see the [TEMPREF](#page-33-1) Register section.

During production testing of the ADuC7023, the TEMPREF register is loaded with an offset adjustment factor. Each part will have a different value in the TEMPREF register. Using this single point calibration, use the same formula as shown:

 $T - T_{REF} = (V_{ADC} - V_{TREF}) \times K$ 

where:

*TREF* is 27°C when using the TEMPREF register method, but is not guaranteed.

*TTREF* can be calculated using the TEMPREF register.

### *TSCON Register*



#### **Table 28. TSCON MMR Bit Designations**



### <span id="page-33-1"></span>*TEMPREF Register*



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### <span id="page-34-0"></span>**BAND GAP REFERENCE**

The ADuC7023 provides an on-chip band gap reference of 2.5 V, which can be used for the ADC and DAC. This internal reference also appears on the  $V_{REF}$  pin. When using the internal reference, a 0.47 µF capacitor must be connected from the external V<sub>REF</sub> pin to AGND to ensure stability and fast response during ADC conversions. This reference can also be connected to an external pin (VREF) and used as a reference for other circuits in the system.

An external buffer is required because of the low drive capability of the  $V_{REF}$  output. A programmable option also allows an external reference input on the  $V_{REF}$  pin.

### *REFCON Register*



### <span id="page-34-1"></span>**Table 30. REFCON MMR Bit Designations**



To connect an external reference source to the ADuC7023, configure REFCON = 0x00. ADC and the DACs can be configured to use the same or different reference resource. See [Table 42.](#page-43-0)

## <span id="page-35-0"></span>NONVOLATILE FLASH/EE MEMORY

The ADuC7023 incorporates Flash/EE memory technology on chip to provide the user with nonvolatile, in-circuit reprogrammable memory space.

Like EEPROM, flash memory can be programmed in-system at a byte level, although it must first be erased. The erase is performed in page blocks. As a result, flash memory is often and more correctly referred to as Flash/EE memory.

The Flash/EE memory represents a step closer to the ideal memory device that includes nonvolatility, in-circuit programmability, high density, and low cost. Incorporated in the ADuC7023, Flash/EE memory technology allows the user to update program code space in-circuit, without needing to replace one-time programmable (OTP) devices at remote operating nodes.

Each part contains a 64 kB array of Flash/EE memory. The lower 62 kB are available to the user, and the upper 2 kB contain permanently embedded firmware, allowing in-circuit serial download. These 2 kB of embedded firmware also contain a power-on configuration routine that downloads factorycalibrated coefficients to the various calibrated peripherals (such as ADC, temperature sensor, and band gap references). This 2 kB embedded firmware is hidden from user code.

### *Flash/EE Memory Reliability*

The Flash/EE memory arrays on the parts are fully qualified for two key Flash/EE memory characteristics: Flash/EE memory cycling endurance and Flash/EE memory data retention.

Endurance quantifies the ability of the Flash/EE memory to be cycled through many program, read, and erase cycles. A single endurance cycle is composed of four independent, sequential events, defined as:

- 1. Initial page erase sequence.
- 2. Read/verify sequence (single Flash/EE).
- 3. Byte program sequence memory.
- 4. Second read/verify sequence (endurance cycle).

In reliability qualification, every half word (16-bit wide) location of the three pages (top, middle, and bottom) in the Flash/EE memory is cycled 10,000 times from 0x0000 to 0xFFFF. As indicated in [Table 1,](#page-4-1) the Flash/EE memory endurance qualification is carried out in accordance with JEDEC Retention Lifetime Specification A117 over the industrial temperature range of −40° to +125°C. The results allow the specification of a minimum endurance figure over a supply temperature of 10,000 cycles.

Retention quantifies the ability of the Flash/EE memory to retain its programmed data over time. Again, the parts are qualified in accordance with the formal JEDEC Retention Lifetime Specification (A117) at a specific junction temperature  $(T_J = 85^{\circ}C)$ . As part of this qualification procedure, the Flash/EE memory is cycled to its specified endurance limit before data retention is characterized. This means that the

Flash/EE memory is guaranteed to retain its data for its fully specified retention lifetime every time the Flash/EE memory is reprogrammed. In addition, note that retention lifetime, based on activation energy of 0.6 eV, derates with  $T_J$  as shown in [Figure 30.](#page-35-2)



*Figure 30. Flash/EE Memory Data Retention*

### <span id="page-35-2"></span><span id="page-35-1"></span>**PROGRAMMING**

The 62 kB of Flash/EE memory can be programmed in circuit, using the serial download mode or the provided JTAG mode.

### *Downloading (In-Circuit Programming) via I2 C*

The ADuC7023 facilitates code download via the the  $I^2C$  port. The parts enter download mode after a reset or power cycle if the BM pin is pulled low through an external 1 kΩ resistor and Flash Addess 0x80014 = 0xFFFFFFFF. Once in download mode, the user can download code to the full 62 kB of Flash/EE memory while the device is in-circuit in its target application hardware. An executable PC I 2 C download is provided as part of the development system for serial downloading via the I 2 C. A USB to I 2 C download dongle can be purchased from Analog Devices, Inc. This board connects to the USB port of a PC and to the I2 C port of the ADuC7023. The part number is USB-I2C/LIN-CONV-Z.

The AN-806 [Application Note](http://www.analog.com/static/imported-files/application_notes/AN806.pdf) describes the protocol for serial downloading via the I<sup>2</sup>C in more detail.

### *JTAG Access*

The JTAG protocol uses the on-chip JTAG interface to facilitate code download and debug.

To access the part via the JTAG interface, the P0.0/BM pin must be set high to enable P0.1/P0.2/P0.3 as JTAG pins.

When debugging, user code should not write to the P0.1/P0.2 and P0.3 pins. If user code toggles any of these pins, JTAG debug pods are not able to connect to the ADuC7023. In case this happens, the user should ensure that Flash Address 0x80014 is erased to allow erasing of the part through the  $I^2C$ interface.
# **SECURITY**

The 62 kB of Flash/EE memory available to the user can be read and write protected.

Bit 31 of the FEEPRO/FEEHIDE MMR (see [Table 34\)](#page-38-0) protects the 62 kB from being read through JTAG programming mode. The other 31 bits of this register protect writing to the flash memory. Each bit protects four pages, that is, 2 kB. Write protection is activated for all types of access.

### *Three Levels of Protection*

Protection can be set and removed by writing directly into FEEHIDE MMR. This protection does not remain after reset.

Protection can be set by writing into FEEPRO MMR. It only takes effect after a save protection command (0x0C) and a reset. The FEEPRO MMR is protected by a key to avoid direct access. The key is saved once and must be entered again to modify FEEPRO. A mass erase sets the key back to 0xFFFF but also erases all the user code.

Flash can be permanently protected by using the FEEPRO MMR and a particular value of key: 0xDEADDEAD. Entering the key again to modify the FEEPRO register is not allowed.

#### <span id="page-36-1"></span>*Sequence to Write the Key*

- 1. Write the bit in FEEPRO corresponding to the page to be protected.
- 2. Enable key protection by setting Bit 6 of FEEMOD (Bit 5 must equal 0).
- 3. Write a 32-bit key in FEEADR, FEEDAT.
- 4. Run the write key command 0x0C in FEECON; wait for the read to be successful by monitoring FEESTA.
- 5. Reset the part.

#### <span id="page-36-0"></span>**Table 31. FEESTA MMR Bit Designations**

To remove or modify the protection, the same sequence is used with a modified value of FEEPRO. If the key chosen is the value 0xDEAD, the memory protection cannot be removed. Only a mass erase unprotects the part, but it also erases all user code.

The sequence to write the key is illustrated in the following example (this protects writing Page 4 to Page 7 of the Flash):



protect the part permanently with FEEADR =  $0xDEAD$  and  $FEEDAT = 0xDEAD$ .

# **FLASH/EE CONTROL INTERFACE**

Serial and JTAG programming use the Flash/EE control interface, which includes the eight MMRs outlined in this section.

#### *FEESTA Register*





# ADuC7023 Data Sheet

# *FEEMOD Register*



# <span id="page-37-0"></span>**Table 32. FEEMOD MMR Bit Designations**



# *FEECON Register*



# <span id="page-37-1"></span>**Table 33. Command Codes in FEECON**



<span id="page-38-2"></span>

*FEEPRO Register*

<sup>1</sup> The FEECON register always reads 0x07 immediately after execution of any of these commands.

### *FEEDAT Register*



# *FEEADR Register*





#### <span id="page-38-0"></span>**Table 34. FEEPRO and FEEHIDE MMR Bit Designations**

cleared by a reset (see [Table 34\)](#page-38-0).

key. The protection settings in FEEHIDE are



#### <span id="page-38-1"></span>*Command Sequence for Executing a Mass Erase*



# **EXECUTION TIME FROM SRAM AND FLASH/EE**

# *Execution from SRAM*

Fetching instructions from SRAM takes one clock cycle because the access time of the SRAM is 2 ns, and a clock cycle is 22 ns minimum. However, if the instruction involves reading or writing data to memory, one extra cycle must be added if the data is in SRAM (or three cycles if the data is in Flash/EE); one cycle to execute the instruction and two cycles to obtain the 32-bit data from Flash/EE. A control flow instruction (a branch instruction, for example) takes one cycle to fetch but also takes two cycles to fill the pipeline with the new instructions.

# *Execution from Flash/EE*

Because the Flash/EE width is 16 bits and the access time for 16-bit words is 22 ns, execution from Flash/EE cannot be completed in one cycle (as can be done from SRAM when the CD bit = 0). Also, some dead times are needed before accessing data for any value of CD bits.

In ARM mode, where instructions are 32 bits, two cycles are needed to fetch any instruction when  $CD = 0$ . In thumb mode, where instructions are 16 bits, one cycle is needed to fetch any instruction.

Timing is identical in both modes when executing instructions that involve using the Flash/EE for data memory. If the instruction to be executed is a control flow instruction, an extra cycle is needed to decode the new address of the program counter, and then four cycles are needed to fill the pipeline. A data processing instruction involving only the core register does not require any extra clock cycles. However, if it involves data in Flash/EE, an extra clock cycle is needed to decode the address of the data, and two cycles are needed to get the 32-bit data from Flash/EE. An extra cycle must also be added before fetching another instruction. Data transfer instructions are more complex and are summarized in [Table 35.](#page-39-0)

<span id="page-39-0"></span>



<sup>1</sup> The SWAP instruction combines an LD and STR instruction with only one fetch, giving a total of eight cycles + 40 ns.

<sup>2</sup> N is the number of data to load or store in the multiple load/store instruction  $(1 < N \le 16)$ .

# **RESET AND REMAP**

The ARM exception vectors are all situated at the bottom of the memory array, from Address 0x00000000 to Address 0x00000020 as shown i[n Figure 31.](#page-39-1) 



<span id="page-39-1"></span>By default, and after any reset, the Flash/EE is mirrored at the bottom of the memory array. The remap function allows the programmer to mirror the SRAM at the bottom of the memory array, which facilitates execution of exception routines from SRAM instead of from Flash/EE. This means exceptions are executed twice as fast, being executed in 32-bit ARM mode with 32-bit wide SRAM instead of 16-bit wide Flash/EE memory.

# *Remap Operation*

When a reset occurs on the ADuC7023, execution automatically starts in factory programmed, internal configuration code. This kernel is hidden and cannot be accessed by user code. If the part is in normal mode (BM pin is high), it executes the power-on configuration routine of the kernel and then jumps to the reset vector address, 0x00000000, to execute the reset exception routine of the user.

Because the Flash/EE is mirrored at the bottom of the memory array at reset, the reset interrupt routine must always be written in Flash/EE.

The remap is done from Flash/EE by setting Bit 0 of the Remap register. Caution must be taken to execute this command from Flash/EE above Address 0x00080020, and not from the bottom of the array because this is replaced by the SRAM.

This operation is reversible. The Flash/EE can be remapped at Address 0x00000000 by clearing Bit 0 of the Remap MMR. Caution must again be taken to execute the remap function from outside the mirrored area. Any type of reset remaps the Flash/EE memory at the bottom of the array.

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## *REMAP Register*



#### <span id="page-40-0"></span>**Table 36. REMAP MMR Bit Designations**



# *Reset Operation*

There are four kinds of reset: external, power-on, watchdog expiration, and software force. The RSTSTA register indicates the source of the last reset, and RSTCLR allows clearing of the RSTSTA register. These registers can be used during a reset exception service routine to identify the source of the reset. If RSTSTA is null, the reset is external.

The RSTCFG register allows different peripherals to retain their state after a watchdog or software reset.

# *RSTSTA Register*





# *RSTCLR Register*



# *RSTCFG Register*



# **Table 38. RSTCFG MMR Bit Designations**



# ADuC7023 Data Sheet



Access: Write

# OTHER ANALOG PERIPHERALS **DAC**

The ADuC7023 incorporates four, 12-bit voltage output DACs on chip. Each DAC has a rail-to-rail voltage output buffer capable of driving 5 kΩ/100 pF.

Each DAC has two selectable ranges:  $0 \text{ V}$  to  $V_{REF}$  (internal band gap 2.5 V reference) and 0 V to  $AV<sub>DD</sub>$ .

The signal range is  $0 \text{ V}$  to  $\text{AV}_{\text{DD}}$ .

By setting RSTCFG Bit 2, the DAC output pins can retain their state during a watchdog or software reset.

# *MMRs Interface*

Each DAC is independently configurable through a control register and a data register. These two registers are identical for the four DACs. Only DAC0CON (see [Table 40\)](#page-42-0) and DAC0DAT (see [Table 41\)](#page-42-1) are described in detail in this section.

# *DACxCON Registers*



# <span id="page-42-0"></span>**Table 40. DAC0CON MMR Bit Designations**



#### *DACxDAT Registers*



#### <span id="page-42-1"></span>**Table 41. DAC0DAT MMR Bit Designations**



# *Using the DACs*

The on-chip DAC architecture consists of a resistor string DAC followed by an output buffer amplifier. The functional equivalent is shown in [Figure 32.](#page-42-2)



*Figure 32. DAC Structure*

<span id="page-42-2"></span>As illustrated i[n Figure 32,](#page-42-2) the reference source for each DAC is user-selectable in software. It can be either  $AV_{DD}$  or  $V_{REF}$ . In 0-to-AV<sub>DD</sub> mode, the DAC output transfer function spans from  $0$  V to the voltage at the AV<sub>DD</sub> pin. In 0-to-V<sub>REF</sub> mode, the DAC output transfer function spans from 0 V to the internal 2.5 V reference, VREF.

The DAC output buffer amplifier features a true, rail-to-rail output stage implementation. This means that when unloaded, each output is capable of swinging to within less than 5 mV of both AV<sub>DD</sub> and ground. Moreover, the DAC linearity specification (when driving a 5 k $\Omega$  resistive load to ground) is guaranteed through the full transfer function except Code 0 to Code 100, and, in 0-to-AV<sub>DD</sub> mode only, Code 3995 to Code 4095.

Linearity degradation near ground and  $V_{DD}$  is caused by saturation of the output amplifier, and a general representation of its effects (neglecting offset and gain error) is illustrated i[n Figure 33.](#page-43-0) The dotted line i[n Figure 33](#page-43-0) indicates the ideal transfer function, and the solid line represents what the transfer function may look like with endpoint nonlinearities due to saturation of the output amplifier[. Figure 33](#page-43-0) represents a transfer function in 0-to- $AV_{DD}$ mode only. In 0-to-VREF mode (with  $V_{REF} < AV_{DD}$ ), the lower nonlinearity is similar. However, the upper portion of the transfer function follows the ideal line right to the end ( $V<sub>REF</sub>$  in this case, not AV<sub>DD</sub>), showing no signs of endpoint linearity errors.



*Figure 33. Endpoint Nonlinearities Due to Amplifier Saturation*

<span id="page-43-0"></span>The endpoint nonlinearities conceptually illustrated in [Figure 33](#page-43-0) get worse as a function of output loading. Most of the ADuC7023 data sheet specifications assume a 5 k $\Omega$  resistive load to ground at the DAC output. As the output is forced to source or sink more current, the nonlinear regions at the top or bottom o[f Figure 33](#page-43-0) become larger, respectively. With larger current demands, this can significantly limit output voltage swing.

# *References to ADC and the DACs*

ADC and DACs can be configured to use internal VREF or an external reference as a reference source. Internal  $V_{REF}$  must work with an external 0.47 µF capacitor.



# **Table 42. Reference Source Selection for ADC and DAC**

# *Configuring DAC Buffers in Op Amp Mode*

In op amp mode, the DAC output buffers are used as an op amp with the DAC itself disabled.

If DACBCFG Bit 0 is set, ADC0 is the positive input to the op amp, ADC1 is the negative input, and DAC0 is the output. In this mode, the DAC should be powered down by clearing Bit 0 and Bit 1 of DAC0CON.

If DACBCFG Bit 1 is set, ADC2 is the positive input to the op amp, ADC3 is the negative input, and DAC1 is the output. In this mode, the DAC should be powered down by clearing Bit 0 and Bit 1 of DAC1CON.

If DACBCFG Bit 2 is set, ADC4 is the positive input to the op amp, ADC5 is the negative input, and DAC2 is the output. In this mode, the DAC should be powered down by clearing Bit 0 and Bit 1 of DAC2CON.

If DACBCFG Bit 3 is set, ADC8 is the positive input to the op amp, ADC9 is the negative input, and DAC3 is the output. In this mode, the DAC should be powered down by clearing Bit 0 and Bit 1 of DAC3CON.

#### *DACBCFG Register*



#### **Table 43. DACBCFG MMR Bit Designations**



### *DACBKEY0 Register*



# **Table 44. DACBCFG Write Sequence**

Access: Write



# **POWER SUPPLY MONITOR**

The power supply monitor regulates the  $IOV<sub>DD</sub>$  supply on the  $ADuC7023$ . It indicates when the  $IOV<sub>DD</sub>$  supply pin drops below a supply trip point. The monitor function is controlled via the PSMCON register. If enabled in the IRQEN or FIQEN register, the monitor interrupts the core using the PSMI bit in the PSMCON MMR. This bit is immediately cleared when CMP goes high.

This monitor function allows the user to save working registers to avoid possible data loss due to low supply or brownout conditions. It also ensures that normal code execution does not resume until a safe supply level has been established.

#### *PSMCON Register*





**Table 45. PSMCON MMR Bit Descriptions**

# **COMPARATOR**

The ADuC7023 integrates voltage comparators. The positive input is multiplexed with ADC2, and the negative input has two options: ADC3 or DAC0. The output of the comparator can be configured to generate a system interrupt, be routed directly to the programmable logic array, start an ADC conversion, or be on an external pin, COMP<sub>OUT</sub>, as shown in [Figure 34.](#page-44-0)



# <span id="page-44-0"></span>*Hysteresis*

[Figure 35](#page-44-1) shows how the input offset voltage and hysteresis terms are defined. Input offset voltage  $(V_{OS})$  is the difference between the center of the hysteresis range and the ground level. This can either be positive or negative. The hysteresis voltage ( $V_H$ ) is  $\frac{1}{2}$  the width of the hysteresis range.



<span id="page-44-1"></span>*Figure 35. Comparator Hysteresis Transfer Function*

# *Comparator Interface*

The comparator interface consists of a 16-bit MMR, CMPCON, which is described i[n Table 46.](#page-45-0)

# *CMPCON Register*



# <span id="page-45-0"></span>**Table 46. CMPCON MMR Bit Descriptions**



# **OSCILLATOR AND PLL—POWER CONTROL**

# *Clocking System*

Each ADuC7023 integrates a 32.768 kHz ± 3% oscillator, a clock divider, and a PLL. The PLL locks onto a multiple (1275) of the internal oscillator or an external 32.768 kHz crystal to provide a stable 41.78 MHz clock (UCLK) for the system. To allow power saving, the core can operate at this frequency, or at binary submultiples of it. The actual core operating frequency, UCLK/2<sup>CD</sup>, is referred to as HCLK. The default core clock is the PLL clock divided by  $8 (CD = 3)$  or  $5.22$  MHz. The core clock frequency can also come from an external clock on the ECLK pin as described in [Figure 36.](#page-46-0) 



#### <span id="page-46-1"></span><span id="page-46-0"></span>**Table 47. Operating Modes**

The selection of the clock source is in the PLLCON register. By default, the part uses the internal oscillator feeding the PLL.

In noisy environments, noise can couple to the external crystal pins, and PLL may quickly lose lock. A PLL interrupt is provided in the interrupt controller. The core clock is immediately halted, and this interrupt is only serviced when the lock is restored.

In case of crystal loss, use the watchdog timer. During initialization, a test on the RSTSTA can determine if the reset came from the watchdog timer.

#### *Power Control System*

A choice of operating modes is available on the ADuC7023. [Table 47](#page-46-1) describes what part is powered on in the different modes and indicates the power-up time.

[Table 48](#page-46-2) gives some typical values of the total current consumption (analog + digital supply currents) in the different modes, depending on the clock divider bits. The ADC is turned off. Note that these values also include current consumption of the regulator and other parts on the test board where these values are measured.



<span id="page-46-2"></span> $X =$  don't care.

#### **Table 48. Typical Current Consumption at 25°C in mA**



# *MMRs and Keys*

The operating mode, clocking mode, and programmable clock divider are controlled via three MMRs, PLLCON (see [Table 49\)](#page-47-0) and POWCONx. PLLCON controls the operating mode of the clock system, POWCON0 controls the core clock frequency and the power-down mode, POWCON1 controls the clock frequency to I<sup>2</sup>C and SPI.

To prevent accidental programming, a certain sequence has to be followed to write to the PLLCON and POWCONx registers.

# *PLLKEY1 Register*



# *PLLKEY2 Register*



# *PLLCON Register*



# <span id="page-47-0"></span>**Table 49. PLLCON MMR Bit Designations**



# **Table 50. PLLCON Write Sequence**



### *POWKEY1 Register*



# *POWKEY2 Register*



# *POWCON0 Register*



### **Table 51. POWCON0 MMR Bit Designations**









# *POWKEY3 Register*



# *POWKEY4 Register*



# *POWCON1 Register*



# **Table 53. POWCON1 MMR Bit Designations**



<sup>1</sup> Divided clock for SPI/I2C0/I2C1 must be greater than or equal to the CPU clock as selected by POWCON0[2:0]

## **Table 54. POWCON1 Write Sequence**



# DIGITAL PERIPHERALS **GENERAL-PURPOSE INPUT/OUTPUT**

<span id="page-49-2"></span>The ADuC7023 provides up to 20 general-purpose, bidirectional I/O (GPIO) pins. All I/O pins are 5 V tolerant, meaning the GPIOs support an input voltage of 5 V. In general, many of the GPIO pins have multiple functions (se[e Table](#page-49-0) 55 for the pin function definitions). By default, the GPIO pins are configured in GPIO mode.

All GPIO pins have an internal pull-up resistor (of about 100 kΩ) and their drive capability is 1.6 mA. Note that a maximum of 20 GPIOs can drive 1.6 mA at the same time. Using the GPxPAR registers, it is possible to enable/disable the pull-up resistors.

The 20 GPIOs are grouped in three ports, Port 0 to Port 2 (Port x). Each port is controlled by four or five MMRs.

The input level of any GPIO can be read at any time in the GPxDAT MMR, even when the pin is configured in a mode other than GPIO. The PLA input is always active.

When the ADuC7023 part enters a power-saving mode, the GPIO pins retain their state. Also note, that by setting RSTCFG bit 0, the GPIO pins can retain their state during a watchdog or software reset.



# <span id="page-49-0"></span>**Table 55. GPIO Pin Function Descriptions**

<sup>1</sup> These pins should not be used by user code when debugging the part via JTAG. Se[e Table 36](#page-40-0) for further details on how to configure these pins for GPIO mode. The default value of these pins depends on the level of the P0.0/BM pin during the last reset sequence.

2 I 2 C1 function is only available on the 32-lead package.

<sup>3</sup> When configured in Mode 2, P1.2 is ECLK by default, or core clock output. To configure it as a clock input, the MDCLK bits in PLLCON must be set to 11.

<sup>4</sup>I<sup>2</sup>C1 function is only available on the 40-lead package.

#### *GPxCON Registers*



GPxCON are the Port x control registers, which select the function of each pin of Port x as described in [Table 56.](#page-49-1)

#### <span id="page-49-1"></span>**Table 56. GPxCON MMR Bit Descriptions**



#### *GP0PAR Register*



#### *GP1PAR Register*



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# *GP2PAR Register*



#### **Table 57. GPxPAR MMR Bit Descriptions**



#### **Table 58. GPIO Drive Strength Control Bits Descriptions**







The drive strength bits can be written one time only after reset. More writing to related bits has no effect on changing drive strength. The GPIO drive strength and pull-up disable is not always adjustable for the GPIO port. Some control bits cannot be changed (see [Table 59\)](#page-50-0).

<span id="page-50-0"></span>



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<sup>1</sup>When P2.0 is configured as AIN12, the internal pull-up resistor cannot be disabled.

#### *GP0DAT Register*



GPxDAT are Port x configuration and data registers. They configure the direction of the GPIO pins of Port x, set the output value for the pins configured as output, and store the input value of the pins configured as input.

# **Table 60. GPxDAT MMR Bit Descriptions**



# *GP0SET Register*



# *GP1SET Register*



# *GP2SET Register*



### **Table 61. GPxSET MMR Bit Descriptions**



# *GP0CLR Registers*



# *GP1CLR Registers*



# *GP2CLR Registers*



### **Table 62. GPxCLR MMR Bit Descriptions**



# **SERIAL PERIPHERAL INTERFACE**

The ADuC7023 integrates a complete hardware serial peripheral interface (SPI) on chip. SPI is an industry standard, synchronous serial interface that allows eight bits of data to be synchronously transmitted and simultaneously received, that is, full duplex up to a maximum bit rate of 20 Mbps.

The SPI port can be configured for master or slave operation and typically consists of four pins: MISO, MOSI, SCLK, and SPISS.

# *MISO (Master In, Slave Out) Pin*

The MISO pin is configured as an input line in master mode and an output line in slave mode. The MISO line on the master (data in) should be connected to the MISO line in the slave device (data out). The data is transferred as byte wide (8-bit) serial data, MSB first.

### *MOSI (Master Out, Slave In) Pin*

The MOSI pin is configured as an output line in master mode and an input line in slave mode. The MOSI line on the master (data out) should be connected to the MOSI line in the slave device (data in). The data is transferred as byte wide (8-bit) serial data, MSB first.

# *SCLK (Serial Clock I/O) Pin*

The master serial clock (SCLK) synchronizes the data being transmitted and received through the MOSI SCLK period. Therefore, a byte is transmitted/received after eight SCLK periods. The SCLK pin is configured as an output in master mode and as an input in slave mode.

In master mode, polarity and phase of the clock are controlled by the SPICON register, and the bit rate is defined in the SPIDIV register as follows:

$$
f_{\text{SERAL CLOCK}} = \frac{f_{\text{UCLK}}}{2 \times (1 + SPIDIV)}
$$

where:

f<sub>UCLK</sub> is the clock selected by POWCON1 Bit 7 to Bit 6.

The maximum speed of the SPI clock is independent on the clock divider bits.

In slave mode, the SPICON register must be configured with the phase and polarity of the expected input clock. The slave accepts data from an external master up to 10 Mbps.

In both master and slave modes, data is transmitted on one edge of the SCLK signal and sampled on the other. Therefore, it is important that the polarity and phase are configured the same for the master and slave devices.

# *SPI Chip Select (SS Input) Pin*

In SPI slave mode, a transfer is initiated by the assertion of SS, which is an active low input signal. The SPI port then transmits and receives 8-bit data until the transfer is concluded by deassertion of  $\overline{SS}$ . In slave mode,  $\overline{SS}$  is always an input.

In SPI master mode, the  $\overline{SS}$  is an active low output signal. It asserts itself automatically at the beginning of a transfer and deasserts itself upon completion.

#### *Configuring External Pins for SPI Functionality*

P1.1 is the slave chip select pin. In slave mode, this pin is an input and must be driven low by the master. In master mode, this pin is an output and goes low at the beginning of a transfer and high at the end of a transfer.

P1.0 is the SCLK pin.

P0.6 is the master in, slave out (MISO) pin.

P0.7 is the master out, slave in (MOSI) pin.

To configure these pins for SPI mode, see th[e General-Purpose](#page-49-2)  [Input/Output](#page-49-2) section.

#### *SPI Registers*

The following MMR registers control the SPI interface: SPISTA, SPIRX, SPITX, SPIDIV, and SPICON.

#### *SPI Status Register*



# **Table 63. SPISTA MMR Bit Designations**







# **Table 64. SPICON MMR Bit Designations**



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# <span id="page-57-0"></span> $l^2C$

The ADuC7023 incorporates two I 2 C peripherals that may be configured as a fully I<sup>2</sup>C-compatible I<sup>2</sup>C bus master device or as a fully I<sup>2</sup>C bus-compatible slave device.

The two pins used for data transfer, SDA and SCL, are configured in a wire-AND format that allows arbitration in a multimaster system. These pins require external pull-up resistors. Typical pull-up values are between 4.7 kΩ and 10 kΩ.

The I<sup>2</sup>C bus peripheral address in the I<sup>2</sup>C bus system is programmed by the user. This ID can be modified any time a transfer is not in progress. The user can configure the interface to respond to four slave addresses.

The transfer sequence of an I 2 C system consists of a master device initiating a transfer by generating a start condition while the bus is idle. The master transmits the slave device address and the direction of the data transfer (read or/write) during the initial address transfer. If the master does not lose arbitration and the slave acknowledges the data, transfer is initiated. This continues until the master issues a stop condition and the bus becomes idle.

The I<sup>2</sup>C peripheral can only be configured as a master or slave at any given time. The same I 2 C channel cannot simultaneously support master and slave modes.

The I<sup>2</sup>C interface on the ADuC7023 includes support for repeated start conditions. In master mode, the ADuC7023 can be programmed to generate a repeated start. In slave mode, the ADuC7023 recognizes repeated start conditions. In master and slave mode, the part recognizes both 7-bit and 10-bit bus addresses. In I<sup>2</sup>C master mode, the ADuC7023 supports continuous reads from a single slave up to 512 bytes in a single transfer sequence. Clock stretching is supported in both master and slave modes. In slave mode, the ADuC7023 can be programmed to return a NACK. This allows the validation of checksum bytes at the end of I2C transfers. Bus arbitration in master mode is supported. Internal and external loopback modes are supported for I2 C hardware testing. In loopback mode. The transmit and receive circuits in both master and slave mode contain 2-byte FIFOs. Status bits are available to the user to control these FIFOs.

# **CONFIGURING EXTERNAL PINS FOR I2 C FUNCTIONALITY**

The I<sup>2</sup>C pins of the ADuC7023 device are P0.4 and P0.5 for I<sup>2</sup>C0 and P0.6 and P0.7 for  $I^2C1$ .

P0.4 and P0.6 are the I<sup>2</sup>C clock signals and P0.5 and P0.7 are the I<sup>2</sup>C data signals. For instance, to configure I<sup>2</sup>C0 pins (SCL0, SDA0), Bit 16 and Bit 20 of the GP0CON register must be set to 1 to enable  $I^2C$  mode. On the other hand, to configure  $I^2C1$  pins (SCL1, SDA1), Bit 25 and Bit 29 of the GP0CON register must be set to 1 to enable I<sup>2</sup>C mode, as shown in the GPIO section. I 2 C1 function is available at P0.6 and P0.7 on 32-lead package and available at P1.6 and P1.7 on 40-lead package.

# **SERIAL CLOCK GENERATION**

The I<sup>2</sup>C master in the system generates the serial clock for a transfer. The master channel can be configured to operate in fast mode (400 kHz) or standard mode (100 kHz).

The bit rate is defined in the I2CDIV MMR as follows:

$$
f_{SERAL\ CLOCK} = \frac{f_{UCLK}}{(2 + DIVH) + (2 + DIVL)}
$$

where:

*fUCLK* is the clock before the clock divider and the clock selected by POWCON1 Bit 4 to Bit 0. *DIVH* is the high period of the clock.

*DIVL* is the low period of the clock.

Thus, for 100 kHz operation,

 $DIVH = DIVI = 0xCF$ 

and for 400 kHz,

 $DIVH = 0x28, DIVL = 0x3C$ 

The I2CDIV register corresponds to DIVH:DIVL.

# <span id="page-57-1"></span>**I 2 C BUS ADDRESSES**

# *Slave Mode*

In slave mode, the registers I2CxID0, I2CxID1, I2CxID2, and I2CxID3 contain the device IDs. The device compares the four I2CxIDx registers to the address byte received from the bus master. To be correctly addressed, the 7MSBs of either ID register must be identical to that of the 7MSBs of the first received address byte. The LSB of the ID registers (the transfer direction bit) is ignored in the process of address recognition.

The ADuC7023 also supports 10-bit addressing mode. When Bit 1 of I2CxSCON (ADR10EN bit) is set to 1, then one 10-bit address is supported in slave mode and is stored in registers I2CxID0 and I2CxID1. The 10-bit address is derived as follows:

I2CxID0[0] is the read/write bit and is not part of the  $I^2C$ address.

 $I2CxID0[7:1] = Address Bits[6:0].$ 

 $I2CxID1[2:0] = Address \; Bits[9:7].$ 

I2CxID1[7:3] must be set to 11110b.

# *Master Mode*

In master mode, the I2CxADR0 register is programmed with the  $I^2C$  address of the device.

In 7-bit address mode, I2CxADR0[7:1] are set to the device address. I2CxADR0[0] is the read/write bit.

In 10-bit address mode, the 10-bit address is created as follows:

I2CxADR0[7:3] must be set to 11110b.  $I2CxADR0[2:1] = Address \text{ bits}[9:8].$  $I2CxADR1[7:0] = Address Bits[7:0].$ I2CxADR0[0] is the read/write bit.

# **I 2 C REGISTERS**

The I2 C peripheral interfaces consists of a number of MMRs. These are described in the following section.

### *I 2 C Master Registers*

#### **I2 C Master Control Registers, I2CxMCON**



#### **Table 65. I2CxMCON MMR Bit Designations**



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# **I2 C Master Status Registers, I2CxMSTA**



Function: These 16-bit MMRs are the I<sup>2</sup>C status registers in master mode.



# **Table 66. I2CxMSTA MMR Bit Designations**

# **I2 C Master Receive Registers, I2CxMRX**



# **I2 C Master Transmit Registers, I2CxMTX**



# **I2 C Master Read Count Registers, I2CxMCNT0**



# **Table 67. I2CxMCNT0 MMR Bit Descriptions: Address = 0xFFFF0810, 0xFFFF0910. Default Value = 0x0000**



# **I2 C Master Current Read Count Registers, I2CxMCNT1**



# **I2 C Address 0 Registers, I2CxADR0**



## **Table 68. I2CxADR0 MMR in 7-Bit Address Mode: Address = 0xFFFF0818, 0xFFFF0918. Default Value = 0x00**



# **Table 69. I2CxADR0 MMR in 10-Bit Address Mode**





# **Table 70. I2CxADR1 MMR in 10-Bit Address Mode**



# **I2 C Master Clock Control Register, I2CxDIV**



#### **Table 72. I2CxSCON MMR Bit Designations**





# CON<sup>t</sup>





# **I2 C Slave Status Registers, I2CxSSTA**



# **Table 73. I2CxSSTA MMR Bit Designations**



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# **I2 C Slave Receive Registers, I2CxSRX**

# Name: I2C0SRX, I2C1SRX Address: 0xFFFF0830, 0xFFFF0930 Default value: 0x00 Access: Read Function: These 8-bit MMRs are the  $I^2C$  slave receive register. **I2 C Slave Transmit Registers, I2CxSTX** Name: I2C0STX, I2C1STX Address: 0xFFFF0834, 0xFFFF0934 Name: I2C0IDx, I2C1IDx Addresses: 0xFFFF093C = I2C1ID0 Default value: 0x00



# **I2 C Hardware General Call Recognition Registers, I2CxALT**



# *I 2 C Common Registers*



# **I2 C Slave Device ID Registers, I2CxIDx**

 $0x$ FFFF083C = I2C0ID0 0xFFFF0940 = I2C1ID1 0xFFFF0840 = I2C0ID1

0xFFFF0944 = I2C1ID2 0xFFFF0844 = I2C0ID2

0xFFFF0948 = I2C1ID3 0xFFFF0848 = I2C0ID3





# **PROGRAMMABLE LOGIC ARRAY (PLA)**

Every ADuC7023 integrates a fully programmable logic array (PLA) consisting of sixteen PLA elements.

Each PLA element contains a two-input look-up table that can be configured to generate any logic output function based on two inputs and a flip-flop. This is represented in [Figure 39.](#page-65-0)



<span id="page-65-0"></span>In total, 20 GPIO pins are available on the ADuC7023 for the PLA. These include 11 input pins and nine output pins, which need to be configured in the GPxCON register as PLA pins before using the PLA.

The PLA is configured via a set of user MMRs. The output(s) of the PLA can be routed to the internal interrupt system, to the CONVSTART signal of the ADC, to an MMR, or to any of the eight PLA output pins.

#### **Table 75. Element Input/Output**



<sup>1</sup> Internal pins only. Read via GPxDAT register.

#### *PLA MMRs Interface*

The PLA peripheral interface consists of the 22 MMRs described in the following sections.

# *PLAELMx Registers*

PLAELMx are Element 0 to Element 15 control registers. They configure the input and output mux of each element, select the function in the look-up table, and bypass/use the flip-flop (see [Table 77\)](#page-66-0).

#### **Table 76. PLAELMx Registers**



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# <span id="page-66-0"></span>**Table 77. PLAELMx MMR Bit Descriptions**

# **Table 78. PLACLK MMR Bit Descriptions Bit Value Description** 31 to 7 Reserved. 6 to 4 Clock source selection. 000 GPIO clock on P0.5. 001 GPIO clock on P1.1. 010 GPIO clock on P1.6. 011 **HCLK.** 100 **External 32.768 kHz crystal.** 101 | Timer1 overflow. 110 **UCLK.** 111 **Internal 32,768 oscillator.** 3 Reserved. 2 to 0 | Clock source selection. 000 GPIO clock on P0.5. 001 GPIO clock on P1.1. 010 GPIO clock on P1.6. 011 **HCLK.** 100 **External 32.768 kHz crystal.** 101 Timer1 overflow. 110 **UCLK.** 111 Internal 32,768 oscillator.

# *PLAIRQ Register*



# **Table 79. PLAIRQ MMR Bit Descriptions**



# *PLACLK Register*



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### **Table 80. Feedback Configuration**



# *PLAADC Register*



# <span id="page-68-0"></span>**Table 81. PLAADC MMR Bit Descriptions**



# *PLADIN Register*



# **Table 82. PLADIN MMR Bit Descriptions**



# **Table 83. PLADOUT MMR Bit Descriptions**





# PULSE-WIDTH MODULATOR **PULSE-WIDTH MODULATOR GENERAL OVERVIEW**

The ADuC7023 integrates a 5-channel pulse-width modulator (PWM) interface. The PWM outputs can be configured to drive an H-bridge or can be used as standard PWM outputs. On power-up, the PWM outputs default to H-bridge mode. This ensures that the motor is turned off by default. In standard PWM mode, the outputs are arranged as three pairs of PWM pins. Users have control over the period of each pair of outputs and over the duty cycle of each individual output.

# **Table 84. PWM MMRs**



In all modes, the PWMxCOMx MMRs control the point at which the PWM outputs change state. An example of the first pair of PWM outputs (PWM0 and PWM1) is shown i[n Figure 40.](#page-69-0) 



<span id="page-69-0"></span>The PWM clock is selectable via PWMCON1 with one of the following values: UCLK divided by 2, 4, 8, 16, 32, 64, 128, or 256. The length of a PWM period is defined by PWMxLEN.

The PWM waveforms are set by the count value of the 16-bit timer and the compare registers contents, as shown with the PWM0 and PWM1 waveforms in [Figure 40.](#page-69-0) 

The low-side waveform, PWM1, goes high when the timer count reaches PWM0LEN, and it goes low when the timer count reaches the value held in PWM0COM2 or when the high-side waveform (PWM0) goes low.

The high-side waveform, PWM0, goes high when the timer count reaches the value held in PWM0COM0, and it goes low when the timer count reaches the value held in PWM0COM1.

# *PWMCON1 Control Register*



# <span id="page-70-0"></span>**Table 85. PWMCON1 MMR Bit Designations**



 $1$  In H-bridge mode, HMODE = 1. See [Table 86](#page-71-0) to determine the PWM outputs.

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On power-up, PWMCON1 defaults to 0x0012 (HOFF = 1 and HMODE = 1). All GPIO pins associated with the PWM are configured in PWM mode by default (see [Table 86\)](#page-71-0). Clear the PWM trip interrupt by writing any value to the PWMCLRI

MMR. Note that when using the PWM trip interrupt, clear the PWM interrupt before exiting the ISR. This prevents generation of multiple interrupts.

# <span id="page-71-0"></span>**Table 86. PWM Output Selection**



 $<sup>1</sup>$  X is don't care.</sup>

 $2$  HS = high side, LS = low side.

#### **Table 87. Compare Registers**




# *PWM1COM0 Compare Register*



Default value: 0x0000

Access: Read/write

register.

Function: PWM4 output pin goes low when the PWM

timer reaches the count value stored in this



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# PROCESSOR REFERENCE PERIPHERALS **INTERRUPT SYSTEM**

There are 22 interrupt sources on the ADuC7023 that are controlled by the interrupt controller. Most interrupts are generated from the on-chip peripherals, such as ADC. Four additional interrupt sources are generated from external interrupt request pins, IRQ0, IRQ1, IRQ2, and IRQ3. The ARM7TDMI CPU core only recognizes interrupts as one of two types, a normal interrupt request IRQ or a fast interrupt request FIQ. All the interrupts can be masked separately.

The control and configuration of the interrupt system is managed through nine interrupt related registers, four dedicated to IRQ, and four dedicated to FIQ. An additional MMR is used to select the programmed interrupt source. The bits in each IRQ and FIQ registers represent the same interrupt source as described in [Table 88.](#page-74-0)

The ADuC7023 contains a vectored interrupt controller (VIC) that supports nested interrupts up to eight levels. The VIC also allows the programmer to assign priority levels to all interrupt sources. Interrupt nesting is enabled by setting the ENIRQN bit in the IRQCONN register. A number of extra MMRs are used when the full-vectored interrupt controller is enabled.

IRQSTA/FIQSTA should be saved immediately upon entering the interrupt service routine (ISR) to ensure that all valid interrupt sources are serviced.

#### <span id="page-74-0"></span>**Table 88. IRQ/FIQ MMRs Bit Description**



### **IRQ**

The interrupt request (IRQ) is the exception signal to enter the IRQ mode of the processor. It is used to service general-purpose interrupt handling of internal and external events.

The four 32-bit registers dedicated to IRQ are: IRQSTA, IRQSIG, IRQEN, and IRQCLR.

#### *IRQSTA Register*





core.

of the different IRQ erates an IRQ bit in the IRQSIG is l. The IRQSIG bits rupt in the pared. All IRQ ne IRQEN MMR.

create the IRQ signal to the ARM7TDMI

#### *IRQEN Register*



#### *IRQCLR Register*



IRQEN bit does not disable this interrupt.

### **FAST INTERRUPT REQUEST (FIQ)**

The fast interrupt request (FIQ) is the exception signal to enter the FIQ mode of the processor. It is provided to service data transfer or communication channel tasks with low latency. The FIQ interface is identical to the IRQ interface and provides the second level interrupt (highest priority). Four 32-bit registers are dedicated to FIQ: FIQSIG, FIQEN, FIQCLR, and FIQSTA.

Bit 31 to Bit 1 of FIQSTA are logically OR'ed to create the FIQ signal to the core and to Bit 0 of both the FIQ and IRQ registers (FIQ source).

The logic for FIQEN and FIQCLR does not allow an interrupt source to be enabled in both IRQ and FIQ masks. A bit set to 1 in FIQEN clears, as a side effect, the same bit in IRQEN. Likewise, a bit set to 1 in IRQEN clears, as a side effect, the same bit in FIQEN. An interrupt source can be disabled in both IRQEN and FIQEN masks.

#### *FIQSIG*

FIQSIG reflects the status of the different FIQ sources. If a peripheral generates an FIQ signal the corresponding bit in the FIQSIG is set, otherwise it is cleared. The FIQSIG bits are cleared when the interrupt in the particular peripheral is cleared. All FIQ sources can be masked in the FIQEN MMR. FIQSIG is read only.

#### **FIQSIG Register**



#### *FIQEN*

FIQEN provides the value of the current enable mask. When a bit is set to 1, the corresponding source request is enabled to create an FIQ exception. When a bit is set to 0, the corresponding source request is disabled or masked which does not create an FIQ exception. The FIQEN register cannot be used to disable an interrupt.

#### **FIQEN Register**



#### *FIQCLR*

FIQCLR is a write-only register that allows the FIQEN register to clear in order to mask an interrupt source. Each bit that is set to 1 clears the corresponding bit in the FIQEN register without affecting the remaining bits. The pair of registers, FIQEN and FIQCLR, allows independent manipulation of the enable mask without requiring an atomic read-modify-write.

This register should only be used to disable an interrupt source when in the interrupt sources interrupt service routine or if the peripheral is temporarily disabled by its own control register.

This register should not be used to disable an IRQ source if that IRQ source has an interrupt pending or could have an interrupt pending.

#### **FIQCLR Register**



#### *FIQSTA*

FIQSTA is a read-only register that provides the current enabled FIQ source status (effectively a logic AND of the FIQSIG and FIQEN bits). When set to 1, that source generates an active FIQ request to the ARM7TDMI core. There is no priority encoder or interrupt vector generation. This function is implemented in software in a common interrupt handler routine.

#### **FIQSTA Register**



#### *Programmed Interrupts*

Because the programmed interrupts are not maskable, they are controlled by another register (SWICFG) that writes into both IRQSTA and IRQSIG registers and/or the FIQSTA and FIQSIG registers at the same time.

The 32-bit register dedicated to software interrupt is SWICFG described in [Table 89.](#page-76-0) This MMR allows the control of a programmed source interrupt.

<span id="page-76-0"></span>



Any interrupt signal must be active for at least the minimum interrupt latency time, to be detected by the interrupt controller and to be detected by the user in the IRQSTA and FIQSTA registers.



### **VECTORED INTERRUPT CONTROLLER (VIC)**

The ADuC7023 incorporates an enhanced interrupt control system or vectored interrupt controller. The vectored interrupt controller for IRQ interrupt sources is enabled by setting Bit 0 of the IRQCONN register. Similarly, Bit 1 of IRQCONN enables the vectored interrupt controller for the FIQ interrupt sources. The vectored interrupt controller provides the following enhancements to the standard IRQ/FIQ interrupts:

- Vectored interrupts allow a user to define separate interrupt service routine addresses for every interrupt source. This is achieved by using the IRQBASE and IRQVEC registers.
- IRQ/FIQ interrupts can be nested up to eight levels depending on the priority settings. An FIQ still has a higher priority than an IRQ. Therefore, if the VIC is enabled for both the FIQ and IRQ and prioritization is maximized, then it is possible to have 16 separate interrupt levels.
- Programmable interrupt priorities, using the IRQP0 to IRQP2 registers, can be assigned an interrupt priority level value between 0 and 7.

#### *VIC MMRs*

#### **IRQBASE Register**

The vector base register, IRQBASE, is used to point to the start address of memory used to store 32 pointer addresses. These pointer addresses are the addresses of the individual interrupt service routines.



#### **Table 90. IRQBASE MMR Bit Designations**



### *IRQVEC Register*

The IRQ interrupt vector register, IRQVEC, points to a memory address containing a pointer to the interrupt service routine of the currently active IRQ. This register should only be read when an IRQ occurs and IRQ interrupt nesting has been enabled by setting Bit 0 of the IRQCONN register.

### **IRQVEC Register**



### **Table 91. IRQVEC MMR Bit Designations**



#### *Priority Registers*

The IRQ interrupt vector register, IRQVEC, points to a memory address containing a pointer to the interrupt service routine of the currently active IRQ. This register should only be read when an IRQ occurs and IRQ interrupt nesting has been enabled by setting Bit 0 of the IRQCONN register.

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### **IRQP0 Register**



### **Table 92. IRQP0 MMR Bit Designations**



# **IRQP1 Register**



# **Table 93. IRQP1 MMR Bit Designations**





# **IRQP2 Register**



### **Table 94. IRQP2 MMR Bit Designations**



#### *IRQCONN Register*

The IRQCONN register is the IRQ and FIQ control register. It contains two active bits. The first to enable nesting and prioritization of IRQ interrupts and the other to enable nesting and prioritization of FIQ interrupts.

If these bits are cleared, then FIQs and IRQs may still be used, but it is not possible to nest IRQs or FIQs. Neither is it possible to set an interrupt source priority level. In this default state, an FIQ does have a higher priority than an IRQ.



#### **Table 95. IRQCONN MMR Bit Designations**



#### *IRQSTAN Register*

If IRQCONN Bit 0 is asserted and IRQVEC is read then one of these bits is asserted. The bit that asserts depends on the priority of the IRQ. If the IRQ is of Priority 0, then Bit 0 asserts. If the IRQ is of Priority 1, then Bit 1 asserts, and so forth. When a bit is set in this register, all interrupts of that priority and lower are blocked.

To clear a bit in this register, all bits of a higher priority must be cleared first. It is only possible to clear one bit at a time. For example, if this register is set to 0x09, then writing 0xFF changes the register to 0x08, and writing 0xFF a second time changes the register to 0x00.



#### **Table 96. IRQSTAN MMR Bit Designations**



#### *FIQVEC Register*

The FIQ interrupt vector register, FIQVEC, points to a memory address containing a pointer to the interrupt service routine of the currently active FIQ. This register should only be read when an FIQ occurs and FIQ interrupt nesting has been enabled by setting Bit 1 of the IRQCONN register.



#### **Table 97. FIQVEC MMR Bit Designations**



#### *FIQSTAN Register*

If IRQCONN Bit 1 is asserted and FIQVEC is read, then one of these bits assert. The bit that asserts depends on the priority of the FIQ. If the FIQ is of Priority 0, then Bit 0 asserts. If the FIQ is of Priority 1, then Bit 1 asserts, and so forth.

When a bit is set in this register, all interrupts of that priority and lower are blocked.

To clear a bit in this register, all bits of a higher priority must be cleared first. It is only possible to clear one bit at a time. For example, if this register is set to 0x09, then writing 0xFF changes the register to 0x08 and writing 0xFF a second time changes the register to 0x00.



#### **Table 98. FIQSTAN MMR Bit Designations**



#### *External Interrupts and PLA interrupts*

The ADuC7023 provides up to four external interrupt sources and two PLA interrupt sources. These external interrupts can be individually configured as level or rising/falling edge triggered.

To enable the external interrupt source or the PLA interrupt source, the appropriate bit must be set in the FIQEN or IRQEN register. To select the required edge or level to trigger on, the IRQCONE register must be appropriately configured.

To properly clear an edge-based external IRQ interrupt or an edgebased PLA interrupt, set the appropriate bit in the IRQCLRE register.

#### **IRQCONE Register**



#### **Table 99. IRQCONE MMR Bit Designations**





### **IRQCLRE Register**



# Data Sheet **ADuC7023**

#### **Table 100. IRQCLRE MMR Bit Designations**



### **TIMERS**

The ADuC7023 has three general-purpose timer/counters: Timer0, Timer1, and Timer2 or Watchdog Timer.

These three timers in their normal mode of operation can be either free-running or periodic.

In free-running mode, the counter decreases from the maximum value until zero scale and starts again at the minimum value. (It also increases from the minimum value until full scale and starts again at the maximum value.)

In periodic mode, the counter decrements/increments from the value in the load register (TxLD MMR) until zero/full scale and starts again at the value stored in the load register.

The timer interval is calculated as follows.

If the timer is set to count down,

$$
Interval = \frac{(TxLD) \times \text{Prescatter}}{\text{Source Clock}}
$$

If the timer is set to count up,

$$
Interval = \frac{(FullScale - TxLD) \times Prescale}{Source Clock}
$$

The value of a counter can be read at any time by accessing its value register (TxVAL). When a timer is being clocked from a clock other than core clock, an incorrect value may be read (due to asynchronous clock system). In this configuration, TxVAL should always be read twice. If the two readings are different, it should be read a third time to get the correct value.

Timers are started by writing in the control register of the corresponding timer (TxCON).

In normal mode, an IRQ is generated each time the value of the counter reaches zero when counting down. It is also generated each time the counter value reaches full scale when counting up. An IRQ can be cleared by writing any value to clear the register of that particular timer (TxCLRI).

When using an asynchronous clock-to-clock timer, the interrupt in the timer block can take more time to clear than the time it takes for the code in the interrupt routine to execute. Ensure that the interrupt signal is cleared before leaving the interrupt service routine. This can be done by checking the IRQSTA MMR.

#### *Hours, Minutes, Seconds, and 1/128 Format*

To use the timer in hours, minutes, seconds,and hundreds format, select the 32768 kHz clock and a prescaler of 256. The hundreds field does not represent milliseconds but 1/128 of a seconds (256/32,768). The bits representing the hour, minute, and second are not consecutive in the register. This arrangement applies to T1LD and T1VAL when using the Hr:Min:Sec:hundreds format as set in T1CON[5:4]. See [Table 101](#page-81-0) for more details.

<span id="page-81-0"></span>



#### *Timer0 (RTOS Timer)*

Timer0 is a general-purpose, 16-bit timer (count-down) with a programmable prescaler (se[e Figure 42\)](#page-81-1). The prescaler source is the core clock frequency (HCLK) and can be scaled by factors of 1, 16, or 256.

Timer0 can be used to start ADC conversions as shown in the block diagram i[n Figure 42.](#page-81-1)



08675-036

<span id="page-81-1"></span>*Figure 42. Timer0 Block Diagram*

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The Timer0 interface consists of four MMRs: T0LD, T0VAL, T0CON, and T0CLRI.

#### *T0LD Register*



Access: Read/write

T0LD is a 16-bit load register that holds the 16-bit value that is loaded into the counter.

#### *T0VAL Register*



T0VAL is a 16-bit read-only register representing the current state of the counter.

#### *T0CON Register*



T0CON is the configuration MMR described in [Table 102.](#page-82-0)

#### <span id="page-82-0"></span>**Table 102. T0CON MMR Bit Descriptions**



#### *T0CLRI Register*



T0CLRI is an 8-bit register. Writing any value to this register clears the interrupt.

### *Timer1 (General-Purpose Timer)*

Timer1 is a general-purpose, 32-bit timer (count down or count up) with a programmable prescaler. The source can be the 32 kHz external crystal, the undivided system, the core clock, or P1.1 (maximum frequency 44 MHz). This source can be scaled by a factor of 1, 16, 256, or 32,768.

The counter can be formatted as a standard 32-bit value or as hours, minutes, seconds, hundredths.

Timer1 has a capture register (T1CAP) that can be triggered by a selected IRQ source initial assertion. This feature can be used to determine the assertion of an event more accurately than the precision allowed by the RTOS timer when the IRQ is serviced.

Timer1 can be used to start ADC conversions as shown in the block diagram i[n Figure 43.](#page-82-1)



<span id="page-82-1"></span>The Timer1 interface consists of five MMRs: T1LD, T1VAL, T1CON, T1CLRI, and T1CAP.

# *T1LD Register*



T1LD is a 32-bit load register that holds the 32-bit value that is loaded into the counter.



T1VAL is a 32-bit read-only register that represents the current state of the counter.

#### *T1CON Register*



T1CON is the configuration MMR described in [Table 103.](#page-83-0)

#### <span id="page-83-0"></span>**Table 103. T1CON MMR Bit Descriptions**





T1CLRI is an 8-bit register. Writing any value to this register clears the Timer1 interrupt.

### *T1CAP Register*



T1CAP is a 32-bit register. It holds the value contained in T1VAL when a particular event occurrs. This event must be selected in T1CON.

#### *Timer2 (Watchdog Time)*

Timer2 has two modes of operation: normal mode and watchdog mode. The watchdog timer is used to recover from an illegal software state. When enabled, it requires periodic servicing to prevent it from forcing a processor reset.

#### **Normal Mode**

Timer2 in normal mode is identical to Timer0, except for the clock source and the count-up functionality. The clock source is 32 kHz from the PLL and can be scaled by a factor of 1, 16, or 256 (see [Figure 44\)](#page-83-1).

<span id="page-83-1"></span>

### **Watchdog Mode**

Watchdog mode is entered by setting Bit 5 in the T2CON MMR. Timer2 decreases from the value present in the T2LD register until 0. T2LD is used as the timeout. The maximum timeout can be 512 sec using the prescaler/256, and full-scale in T2LD. Timer3 is clocked by the internal 32 kHz crystal when operating in the watchdog mode. To enter watchdog mode successfully, Bit 5 in the T2CON MMR must be set after writing to the T2LD MMR.

If the timer reaches 0, a reset or an interrupt occurs, depending on Bit 1 in the T2CON register. To avoid reset or interrupt, any value must be written to T2CLRI before the expiration period. This reloads the counter with T2LD and begins a new timeout period.

When watchdog mode is entered, T2LD and T2CON are writeprotected. These two registers cannot be modified until a reset clears the watchdog enable bit, which causes Timer2 to exit watchdog mode.

The Timer2 interface consists of four MMRs: T2LD, T2VAL, T2CON, and T2CLRI.

#### *T2LD Register*



T2LD is a 16-bit register load register that holds the 16-bit value that is loaded into the counter.

#### *T2VAL Register*

Access: Read



T2VAL is a 16-bit read-only register that represents the current state of the counter.

### *T2CON Register*



T2CON is the configuration MMR described in [Table 104.](#page-84-0)

<span id="page-84-0"></span>



### *T2CLRI Register*



T2CLRI is an 8-bit register. Writing any value to this register on successive occassions clears the Timer2 interrupt in normal mode or resets a new timeout period in watchdog mode*.* 

The user must perform successive writes to this register to ensure resetting the timeout period.

### *Secure Clear Bit (Watchdog Mode Only)*

The secure clear bit is provided for a higher level of protection. When set, a specific sequential value must be written to T2CLRI to avoid a watchdog reset. The value is a sequence generated by the 8-bit linear feedback shift register (LFSR) polynomial = X8  $+ X6 + X5 + X + 1$  shown i[n Figure 45.](#page-85-0)

The initial value or seed is written to T2CLRI before entering watchdog mode. After entering watchdog mode, a write to T2CLRI must match this expected value. If it matches, the LFSR is advanced to the next state when the counter reload happens. If it fails to match the expected state, a reset is immediately generated, even if the count has not yet expired.

The value 0x00 should not be used as an initial seed due to the properties of the polynomial. The value 0x00 is always guaranteed to force an immediate reset. The value of the LFSR cannot be read; it must be tracked/generated in software.

An example of a sequence follows:

- 1. Enter initial seed, 0xAA, in T2CLRI before starting Timer2 in watchdog mode.
- 2. Enter 0xAA in T2CLRI; Timer2 is reloaded.
- 3. Enter 0x37 in T2CLRI; Timer2 is reloaded.
- 4. Enter 0x6E in T2CLRI; Timer2 is reloaded.
- 5. Enter 0x66. 0xDC was expected; the watchdog resets the chip.

<span id="page-85-0"></span>

*Figure 45. 8-Bit LFSR*

# <span id="page-86-2"></span>HARDWARE DESIGN CONSIDERATIONS **POWER SUPPLIES**

The ADuC7023 operational power supply voltage range is 2.7 V to 3.6 V. Separate analog and digital power supply pins  $(AV_{DD})$ and  $\text{IOV}_{\text{DD}}$ , respectively) allow  $\text{AV}_{\text{DD}}$  to be kept relatively free of noisy digital signals often present on the system  $IOV<sub>DD</sub>$  line. In this mode, the part can also operate with split supplies, that is, it can use different voltage levels for each supply. For example, the system can be designed to operate with an IOV<sub>DD</sub> voltage level of 3.3 V while the AV<sub>DD</sub> level can be at 3 V, or vice versa. A typical split supply configuration is shown in [Figure 46.](#page-86-0)



*Figure 46. External Dual Supply Connections*

<span id="page-86-0"></span>As an alternative to providing two separate power supplies, the user can reduce noise on AV<sub>DD</sub> by placing a small series resistor and/or ferrite bead between  $AV_{DD}$  and  $IOV_{DD}$ , and then decoupling  $AV<sub>DD</sub>$  separately to ground. An example of this configuration is shown i[n Figure 47.](#page-86-1) With this configuration, other analog circuitry (such as op amps, voltage reference, and others) can be powered from the AV<sub>DD</sub> supply line as well.



*Figure 47. External Single Supply Connections*

<span id="page-86-1"></span>In bot[h Figure 46](#page-86-0) an[d Figure 47,](#page-86-1) a large value (10  $\mu$ F) reservoir capacitor sits on  $IOV<sub>DD</sub>$ , and a separate 10  $µF$  capacitor sits on  $AV_{DD}$ . In addition, local small-value (0.1  $\mu$ F) capacitors are located at each  $AV_{DD}$  and  $IOV_{DD}$  pin of the chip. As per standard design practice, include all of these capacitors and ensure the smaller capacitors are close to each AV<sub>DD</sub> pin with trace lengths as short as possible. Connect the ground terminal of each of these capacitors directly to the underlying ground plane.

Finally, the analog and digital ground pins on the ADuC7023 must be referenced to the same system ground reference point at all times.

### *IOV<sub>DD</sub>* Supply Sensitivity

The IOV<sub>DD</sub> supply is sensitive to high frequency noise because it is the supply source for the internal oscillator and PLL circuits. When the internal PLL loses lock, the clock source is removed by a gating circuit from the CPU, and the ARM7TDMI core stops executing code until the PLL regains lock. This feature is to ensure that no flash interface timings or ARM7TDMI timings are violated.

Typically, frequency noise greater than 50 kHz and 50 mV p-p on top of the supply causes the core to stop working.

If decoupling values recommended in the Power Supplies section do not sufficiently dampen all noise soures below 50 mV on  $IOV<sub>DD</sub>$ , a filter such as the one shown i[n Figure 48](#page-86-3) is recommended.



*Figure 48. Recommended IOV<sub>DD</sub> Supply Filter* 

#### <span id="page-86-3"></span>*Linear Voltage Regulator*

Each ADuC7023 requires a single 3.3 V supply, but the core logic requires a 2.6 V supply. An on-chip linear regulator generates the 2.6 V from IOV $_{DD}$  for the core logic. The LV $_{DD}$  pin is the 2.6 V supply for the core logic. An external compensation capacitor of 0.47  $\mu$ F must be connected between LV<sub>DD</sub> and DGND (as close as possible to these pins) to act as a tank of charge, as shown in [Figure 49.](#page-86-4)



*Figure 49. Voltage Regulator Connections*

<span id="page-86-4"></span>The  $LV_{DD}$  pin should not be used for any other chip. It is also recommended to use excellent power supply decoupling on IOV<sub>DD</sub> to help improve line regulation performance of the on-chip voltage regulator.

# **GROUNDING AND BOARD LAYOUT RECOMMENDATIONS**

As with all high resolution data converters, special attention must be paid to grounding and PC board layout of the ADuC7023-based designs to achieve optimum performance from the ADCs and DACs.

Although the parts have separate pins for analog and digital ground (AGND and DGND), the user must not tie these to two separate ground planes unless the two ground planes are connected very close to the part. This is illustrated in the simplified example shown i[n Figure 50a](#page-87-0). In systems where digital and analog ground planes are connected together somewhere else (at the system power supply, for example), the planes cannot be reconnected near the part because a ground loop would result. In these cases, tie all the ADuC7023 AGND and DGND pins to the analog ground plane, as illustrated i[n Figure 50b](#page-87-0). In systems with only one ground plane, ensure that the digital and analog components are physically separated onto separate halves of the board so that digital return currents do not flow near analog circuitry (and vice versa).

The ADuC7023 can then be placed between the digital and analog sections, as illustrated i[n Figure 50c](#page-87-0).



<span id="page-87-0"></span>In all of these scenarios, and in more complicated real-life applications, users should pay particular attention to the flow of current from the supplies and back to ground. Make sure the return paths for all currents are as close as possible to the paths the currents took to reach their destinations.

For example, do not power components on the analog side (as seen in [Figure 50b](#page-87-0)) with  $\mathrm{IOV_{DD}}$  because that would force return currents from IOV<sub>DD</sub> to flow through AGND. Avoid digital currents flowing under analog circuitry, which can occur if a noisy digital chip is placed on the left half of the board (shown in [Figure 50c](#page-87-0)). If possible, avoid large discontinuities in the ground plane(s) such as those formed by a long trace on the same layer, because they force return signals to travel a longer path. In addition, make all connections to the ground plane directly, with little or no trace separating the pin from its via to ground.

When connecting fast logic signals (rise/fall time < 5 ns) to any of the ADuC7023 digital inputs, add a series resistor to each relevant line to keep rise and fall times longer than 5 ns at the input pins of the part. A value of 100  $\Omega$  or 200  $\Omega$  is usually sufficient enough to prevent high speed signals from coupling capacitively into the part and affecting the accuracy of ADC conversions.

# **CLOCK OSCILLATOR**

The clock source for the ADuC7023 can be generated by the internal PLL or by an external clock input. To use the internal PLL, connect a 32.768 kHz parallel resonant crystal between XCLKI and XCLKO, and connect a capacitor from each pin to ground, as shown in [Figure 51.](#page-87-1) The crystal allows the PLL to lock correctly to give a frequency of 41.78 MHz. If no external crystal is present, the internal oscillator is used to give a typical frequency of 41.78 MHz  $\pm$  3%.



*Figure 51. External Parallel Resonant Crystal Connections*

<span id="page-87-1"></span>To use an external source clock input instead of the PLL (see [Figure 52\)](#page-87-2), Bit 1 and Bit 0 of PLLCON must be modified. The external clock uses P1.1 and XCLK.



*Figure 52. Connecting an External Clock Source*

<span id="page-87-2"></span>Using an external clock source, the ADuC7023 specified operational clock speed range is 50 kHz to 44 MHz  $\pm$  1%, which ensures correct operation of the analog peripherals and Flash/EE.

# Data Sheet **ADuC7023**

### **POWER-ON RESET OPERATION**

An internal power-on reset (POR) is implemented on the ADuC7023. For LV<sub>DD</sub> below 2.40 V typical, the internal POR holds the part in reset. As LV<sub>DD</sub> rises above 2.40 V, an internal timer times out for typically 64 ms before the part is released from reset. The user must ensure that the power supply  $\text{IOV}_{\text{DD}}$ has reached a stable 2.7 V minimum level by this time. Likewise, on power-down, the internal POR holds the part in reset until LV<sub>DD</sub> has dropped below 2.40 V.

[Figure 53](#page-88-0) illustrates the operation of the internal POR in detail.



<span id="page-88-0"></span>*Figure 53. Internal Power-On Reset Operation*

# **TYPICAL SYSTEM CONFIGURATION**

A typical ADuC7023 configuration is shown i[n Figure 54.](#page-89-0) It summarizes some of the hardware considerations. The bottom of the LFCSP package has an exposed pad that needs to be soldered to a metal plate on the board for mechanical reasons. The metal plate of the board can be connected to ground.



<span id="page-89-0"></span>*Figure 54. Typical System Configuration*

# DEVELOPMENT TOOLS **PC-BASED TOOLS**

Four types of development systems are available for the ADuC7023 family. The ADuC7023 QuickStart Plus is intended for new users who want to have a comprehensive hardware development environment.

These systems consist of the following PC-based (Windows® compatible) hardware and software development tools.

#### *Hardware*

The hardware system uses the ADuC7023 evaluation board, a serial port programming cable, and a RDI-compliant JTAG emulator (included in the ADuC7023 QuickStart Plus only).

### *Software*

The software system has an integrated development environment, incorporating an assembler, compiler, and nonintrusive JTAGbased debugger. The software sytem uses a serial downloader software and example code.

### *Miscellaneous*

The miscellaneous systems use CD-ROM documentation.

### **IN-CIRCUIT I 2 C DOWNLOADER**

An I<sup>2</sup>C-based serial downloader is available at www.analog.com. This software requires an USB-to-I 2 C adaptor board available from Analog Devices. The part number for this USB-to-I 2 C adapter is USB-I2C/LIN-CONV-Z.

# OUTLINE DIMENSIONS



*Dimensions shown in millimeters*

# <span id="page-92-0"></span>**ORDERING GUIDE**



<sup>1</sup> Z = RoHS Compliant Part.

# **NOTES**

# **NOTES**

# **NOTES**

I 2 C refers to a communications protocol originally developed by Philips Semiconductors (now NXP Semiconductors).

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